# **MLX75027 VGA Time-of-Flight Sensor**

PRELIMINARY DATASHEET v0.7

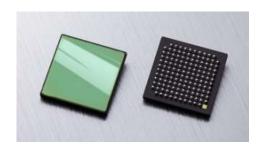
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## **Features & Benefits**

- 1/2" optical Time-of-Flight image sensor
- VGA (640 x 480) pixel array
- 10 x 10 μm DepthSense® pixels
- Integrated microlenses
- Backside illumination (BSI technology)
- External quantum efficiency 44.3% (850nm)
- External quantum efficiency 25.5% (940nm)
- High distance accuracy due to programmable modulating frequencies up to 100 MHz
- AC Demodulation contrast >85 % (50 MHz)
- AC Demodulation contrast >69 % (100 MHz)
- Differential light source control with phase delay feedback loop
- Full resolution distance framerate of max. 135 FPS (4 phases, Tint 300μs, 4lane data @960mbps MIPI configuration)
- Up to 8 raw phases (or quads) per frame
- Per-phase statistics & diagnostics
- Continuous or triggered operation mode(s)
- Configurable over I<sup>2</sup>C (up to 400kHz)
- CSI-2 serial data output, MIPI D-PHY, 1 clock lane, 2 or 4 data lanes (< 960 Mbps/lane)</li>
- Build-in temperature sensor
- Region of interest (ROI) selection
- Integrated support for binning (2x2, 4x4, 8x8)
- Horizontal mirror & vertical flip image modes
- 14 x 14 x 2.2 mm ceramic BGA package
- Number of pins = 141
- Ambient operating temperature range of -40 - 105°C
- AEC-Q100 qualified (grade 2)

# **Description**

MLX75027 is a fully integrated optical Time-of-Flight image sensor. It's perfectly suited for automotive applications, including, but not limited to, gesture recognition, monitoring, skeleton tracking, people or obstacle detection and traffic monitoring. The sensor features a VGA (640x480) pixel array based on the DepthSense® pixel technology. Combined with a modulated light source this sensor is capable of measuring object distance and reflectivity under extreme background light conditions. This distance information can be used to calculate a complete 3D point cloud representation of a scene. Full resolution image acquisition up to 135 distance frames per second while supplied to a microcontroller via a standardized MIPI CSI-2 serial camera interface. The device is available in a ceramic BGA package and offers a variety of integration possibilities.



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# **Document Revision History**

| Version   | Date       | Changes   |
|-----------|------------|---|
| 0.1 - 0.6 | 11.07.2017 | Draft version(s)  |
| 0.7       | 04.06.2019 | Added registers 0x10D2, 0x10D3 0x2COC, 0x2COD, 0x5281, 0x5282, 0x5283 to the initialization map in section 6.2  Removed input clock related registers 0x1006, 0x1007, 0x1042, 0x1046, 0x104A and added them directly to the initialization map in section 6.2  Added RANDNM7 parameter as part of PREMIX feature in section 7.12  Added PLLSETUP, PIXRESET & RANDNM0 parameters in section 7.4  Updated External Decoupling in block diagram in section 2  Updated SLASEL description in section 5.1.6  Simplified FMOD calculation in section 7.7  Corrected description of 0x4EA0 in section 7.14 |

Table 1 : Changelog

# **Ordering Information**

| Product  | Temperature<br>Rating | Package<br>Identifier | Option<br>Code | Packing Style |
|----------|-----------------------|-----------------------|----------------|---------------|
| MLX75027 | R                     | TC                    | ABA-200        | TR            |
| MLX75027 | R                     | TC                    | ABA-210        | TR            |

Table 2 : Device ordering information

| Temperature Rating             | R : -40°C to 105°C  |
|--------------------------------|---|
| Package Identifier             | TC : Ceramic ball grid array  |
| Option Code                    | AAA-200 : engineering samples (obsolete)  ABA-200 : incl. double sided ARC coating, no optical filter  (available in sample pack of 10 pieces)  ABA-210 : version AAA-200 with cover tape |
| Packing Style Ordering Example | TR : Tray MLX75027RTC-ABA-200-TR  |

Table 3



# 1. System Architecture

A complete TOF system or camera module includes at least these components:

- MLX75027 VGA (640x480 pixels) TOF pixel array
- A synchronized high bandwidth near infrared (NIR) active illumination source
- Beam shaping optics for the light distribution
- A receiving sensor lens (optimized for maximum NIR wavelength transmittance)
- A microprocessor, DSP, FPGA or SOC (system on chip) to calculate and process the data, compatible with MIPI camera serial interface CSI-2

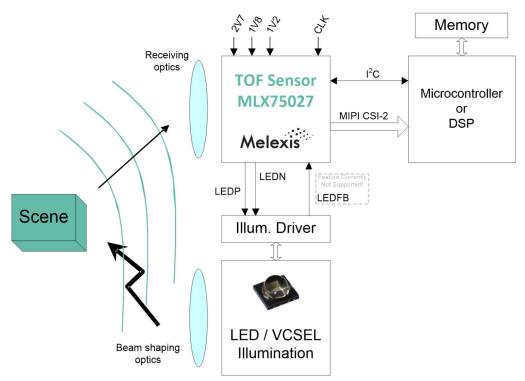


Figure 1 : System block diagram



# 2. Sensor Block Diagram

MLX75027 is a Time-of-Flight (TOF) camera sensor with two tap Current Assisted Photo Demodulator (CAPD) pixels offering high responsivity. These backside illuminated pixels are connected to low noise analog amplifiers and converted by column ADCs which enable high speed & accurate image acquisition. Furthermore it consists of an PLL timing generator, a high speed CSI2 serial interface, controllable registers via I<sup>2</sup>C and a digital control unit in charge of the different internal blocks.

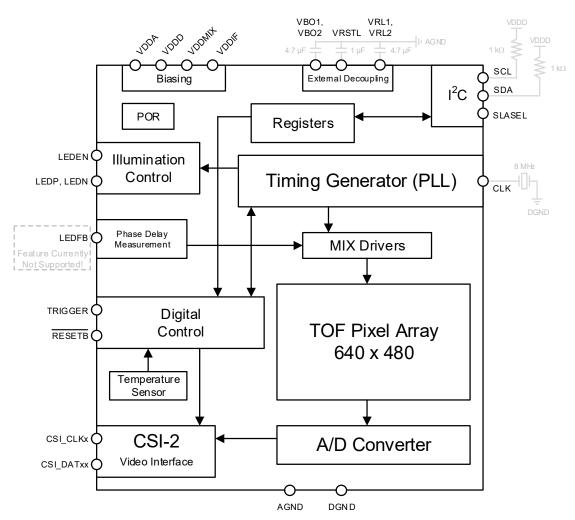


Figure 2 : Sensor block diagram



# 3. Electrical Specifications

# 3.1. Absolute Maximum Ratings

| Parameter                    | Symbol | Min. | Max. | Unit |
|------------------------------|--------|------|------|------|
| Supply voltage (analog)      | VDDA   | -0.3 | 3.3  | V    |
| Supply voltage (MIX drivers) | VDDMIX | -0.3 | 1.8  | V    |
| Supply voltage (digital)     | VDDD   | -0.3 | 1.8  | V    |
| Supply voltage (interfaces)  | VDDIF  | -0.3 | 3.3  | V    |
| Input voltage (digital IOs)  |        | -0.3 | 3.3  | V    |

Note: Absolute maximum ratings should not be exceeded at any time to avoid permanent hardware damage.

# 3.2. Typical Operating Conditions

| Parameter   | Min.      | Тур.    | Max.  | Unit |
|---|-----------|---------|-------|------|
| LEDP, LEDN single ended high level<br>(current of -2mA, LVDS_EN = 0)<br>LEDEN | VIF - 0.2 |         |       | V    |
| LEDP, LEDN single ended low level<br>(current of 2mA, LVDS_EN = 0)<br>LEDEN   |           |         | 0.2   | V    |
| LEDP/LEDN differential common mode (LVDS_EN = 1)                              | 0.765     | VIF / 2 | 1.015 | mV   |
| LEDP/LEDN differential swing (with R = 100k $\Omega$ , LVDS_EN = 1)           | 100       | 150     | 250   | mV   |
| LEDP, LEDN termination resistor   |           | 100     |       | Ohm  |
| Minimum TRIGGER pulse length  |           | 1       |       | μs   |
| Minimum RESETB pulse  |           | 1       |       | μs   |
| Junction to Ambient Thermal Resistance  |           | 25      |       | K/W  |
| Operating ambient temperature   | -40       |         | 105   | degC |

### 3.3. Video Interface

MLX75027 is fully compliant with the hardware description as described in the MIPI Alliance Specification for D-PHY version 1.20.00, released in September 2014.



### 3.4. Power Consumption

|                                |        | Applica           | tion A            | Application B     |                   |                    |      |
|--------------------------------|--------|-------------------|-------------------|-------------------|-------------------|--------------------|------|
| Parameter                      | Symbol | Typ. <sup>1</sup> | Max. <sup>2</sup> | Typ. <sup>1</sup> | Max. <sup>2</sup> | Peak. <sup>3</sup> | Unit |
| Analog Supply Voltage          | VDDA   | 2.7 ± 0.1         |                   | 2.7 ± 0.1         |                   |                    | V    |
| Analog Supply Current          | IDDA   | 10.5              | 10.8              | 15.6              | 16                | 39                 | mA   |
| MIX Drivers Supply Voltage     | VDDMIX | 1.2 ± 0.1         |                   | 1.2 ± 0.1         |                   |                    | V    |
| MIX Drivers Supply Current     | IDDMIX | 69.9              | 101.3             | 292.9             | 424.7             | 2784               | mA   |
| Digital Supply Voltage         | VDDD   | 1.2 ± 0.1         |                   | 1.2 ± 0.1         |                   |                    | V    |
| Digital Supply Current         | IDDD   | 87.8              | 100.7             | 104.4             | 119.8             | 181                | mA   |
| I/O Supply Voltage             | VDDIF  | $1.8 \pm 0.1$     |                   | $1.8 \pm 0.1$     |                   |                    | V    |
| I/O Supply Current             | IDDIF  | 1.9               | 2.2               | 2.3               | 2.6               | 3                  | mA   |
| Power Consumption <sup>5</sup> | Р      | 221               | 275               | 523               | 757.6             |                    | mW   |

 $Note^1$ : Typical values are the average power consumption with nominal voltage levels (at room temperature) for two defined application conditions.

#### Application A: Typical

- Full resolution (640x480 pixels)
- 4 raw phases per distance frame
- 30 distance frames per second
- 250 μs integration time
- 60 MHz modulation frequency
- 800 mbps ( 4 lane MIPI data rate )

#### Application B : Performance

- Full resolution (640x480 pixels)
- 4 raw phases per distance frame
- 60 distance frames per second
- 600 μs integration time
- = 000 µs integration time
- 100 MHz modulation frequency
- 960 mbps ( 4 lane MIPI data rate )

Note<sup>2</sup>: Maximum values are typical values in worst case conditions<sup>4</sup>

Note<sup>3</sup>: Peak values are the maximum instant current during the most active period in worst case conditions<sup>4</sup>

 $Note ^4: Worst \ case \ conditions \ take \ into \ account \ manufacturing \ process \ variation \ \& \ the \ full \ ambient \ temperature \ range$ 

Note<sup>5</sup>: The total power consumption is dominated by the integration duty cycle,

calculated as 4 \* integration time (in  $\mu$ s) \* distance FPS /  $10^4$ , as shown in Figure 3.

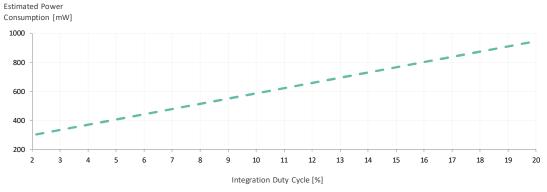


Figure 3: Maximum device power consumption in function of the integration duty cycle



#### 3.5. Maximum Distance Frame Rate

The maximum distance frame rate that can be achieved depends on the integration time and minimum readout time per phase and the total amount of raw phases for each distance frame.

The phase readout time is determined by the MIPI configuration settings as explained in section 7.4.

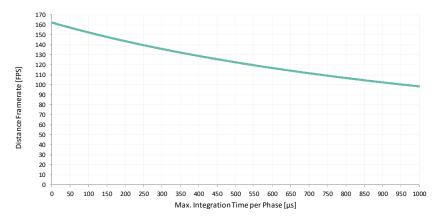


Figure 4: Theoretical Maximum Distance Frame Rate in function of Integration Time (per phase)

Figure 4 presents the theoretical maximum distance frame rate for a 4 lane data output at 960 mbps, however it does not take into account any thermal limitations. Higher integration time also increases the power consumption (Figure 3) and thus device self-heating. For safe operation within the automotive ambient temperature range of -40 - 105 °C this self-heating must be limited to 20 °C. Each PCB design has a unique thermal behaviour, but a typical junction to ambient thermal resistance ( $\theta_{JA}$ ) of 25 K/W would limit the sensor power consumption to 800 mW, corresponding to an illumination duty cycle of 16%.

A review of the theoretical maximum distance frame rate with these thermal limitations results in an updated maximum distance frame rate as shown in Figure 5.

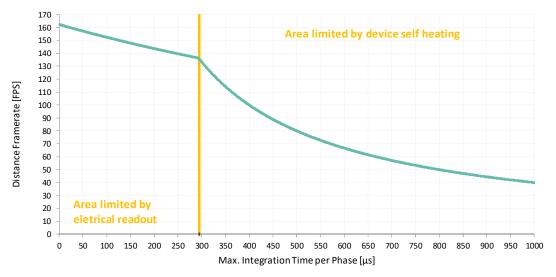


Figure 5: Practical Maximum Distance Frame Rate in function of Integration Time (per phase)



### 3.6. Decoupling Recommendations

It is generally known that sensor performance can degrade with noisy input supplies. Specifications in this datasheet are only valid when stable voltage levels are available. Common decouple techniques use a two-step architecture consisting of a small capacitor (~10-100nF) as close as possible to the supply pin, combined with a bigger capacitor further away from the device, both connected to a low impedance ground plane to minimize inductance. Additionally a small series ferrite bead can be used to keep high frequency noise outside of the IC, but also to keep internally generated noise from propagating to the rest of the system.

#### **External Voltage Supplies**

VDDA : min. 4.7μF

VDDMIX : min. 100nF & 4.7μF
 VDDD : min. 100nF & 4.7μF
 VIF : min. 100nF & 1μF

#### **Internal Generated Voltage Supplies**

VBO1, VBO2 : min. 4.7μF

VRSTL : min. 1μF
 VRL1, VRL2 : min. 4.7μF

These recommendations are based on analysis of different available hardware platforms. Each new hardware design requires an individual analysis to find & optimize the correct decoupling strategy.

### 3.7. Power-up Sequence

VDDD and VDDMIX use 1V2 as supply and it is possible to combine them on a single regulator source. However, VDDMIX exhibits high peak currents during the integration time that could compromise the stability of VDDD. Instantaneous voltage drops on VDDD need to be avoided and it is recommended to use two separate regulators instead. In this scenario it is mandatory that VDDD is enabled before VDDMIX, and that VDDMIX is disabled before VDDD on power-down.

More detailed power-up timings can be found in chapter 6.

A slew rate of max. 25 mV/µs has been specified for each power supply to avoid oscillations during power-up.

## 3.8. Input Clock Requirements

MLX75027 requires a fixed clock input signal of 8 MHz generated by an external crystal oscillator.

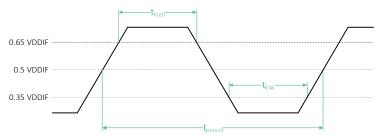


Figure 6: CLK square waveform input diagram

| Parameter            | Symbol              | Min. | Тур. | Max. | Unit |
|----------------------|---------------------|------|------|------|------|
| CLK high level       | CLK <sub>HIGH</sub> | 1.2  |      |      | V    |
| CLK low level        | $CLK_{LOW}$         |      |      | 0.6  | V    |
| CLK frequency        |                     |      | 8    |      | MHz  |
| CLK low level width  | $t_{low}$           | 50   | 62.5 | 75   | ns   |
| CLK high level width | t <sub>high</sub>   | 50   | 62.5 | 75   | ns   |
| CLK jitter           |                     |      |      | 600  | ps   |

Table 4 : CLK input characteristics



# 3.9. I<sup>2</sup>C Specifications

MLX75027 features a standard (up to 400 kHz) inter-integrated circuit communication interface, known as  $I^2C$ . The sensor operates as  $I^2C$  slave with default slave address of 0x67. This address can be changed via the external PIN SLASEL (more information can be found in section 5.1.6). The master  $I^2C$  device is responsible to initiate all communication, it is in control of the clock line (SCL) & sends data via the SDA line. Each  $I^2C$  slave on the bus monitors this communication and will respond to the master when requested.

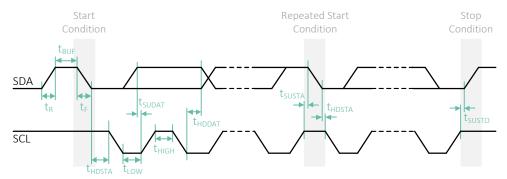


Figure 7: I<sup>2</sup>C serial communication diagram

| Parameter                | Symbol                             | Condition                                   | Min.           | Max.      | Unit |
|--------------------------|------------------------------------|---|----------------|-----------|------|
| Low level input voltage  | $V_{IL}$                           |   | -0.3           | 0.3*VDDIF | V    |
| High level input voltage | $V_{IH}$                           |   | 0.7*VDDIF      | 1.9       | V    |
| Low level output voltage | V <sub>OL</sub><br>V <sub>OL</sub> | VDDIF > 2V, sink 3mA                        | 0<br>0.8*VDDIF | 0.3*VDDIF | V    |
| Output fall time         | t <sub>of</sub>                    | Load 10pF - 400 pF<br>0.7*VDDIF - 0.3*VDDIF |                | 250       | ns   |
| Input current            | I <sub>i</sub>                     | 0.1*VDDIF - 0.9*VDDIF                       | -10            | 10        | μΑ   |
| SDA I/O capacitance      | C <sub>I/O</sub>                   |   |                | 10        | pF   |
| SCL input capacitance    | CI                                 |   |                | 10        | pF   |

Table 5: I<sup>2</sup>C Electrical Specifications

| Parameter                                      | Symbol                    | Min. | Max. | Unit |
|--|---------------------------|------|------|------|
| SCL clock frequency                            | $f_{SCL}$                 | 0    | 400  | kHz  |
| Rise time (SCD & SCL)                          | $t_R$                     |      | 300  | ns   |
| Fall time (SDA & SCL)                          | $t_{\scriptscriptstyleF}$ |      | 300  | ns   |
| Hold time (start condition)                    | $t_{\text{HDSTA}}$        | 0.6  |      | ns   |
| Setup time (repstart condition)                | t <sub>SUSTA</sub>        | 0.6  |      | μs   |
| Setup time (stop condition)                    | $t_{\text{SUSTO}} \\$     | 0.6  |      | μs   |
| Data setup time                                | t <sub>SUDAT</sub>        | 100  |      | μs   |
| Data hold time                                 | $t_{\text{HDDAT}}$        | 0    | 0.9  | μs   |
| Bus free time between stop and start condition | t <sub>BUF</sub>          | 1.3  |      | μs   |
| Low period of the SCL clock                    | $t_{\text{LOW}}$          | 1.3  |      | μs   |
| High period of the SCL clock                   | t <sub>HIGH</sub>         | 0.6  |      | μs   |

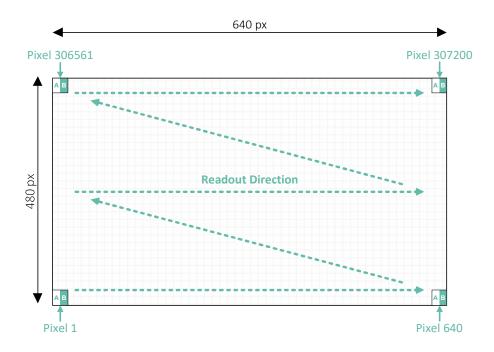
Table 6 :  $I^2C$  Fast Mode Specifications



# 4. Optical Characteristics

# 4.1. VGA Pixel Array Configuration

The pixel array has a total of 640 x 480 DepthSense® pixels. Each pixel consists of 2 individual taps called tap A and tap B. Information from both taps is needed for a reliable distance calculation. The data format (or output modes) available via the MIPI CSI2 video interface can be selected by the user and are described in more detail in section 7.3. The pixels are read out from bottom left, to top right, first horizontally, afterwards vertically, like indicated in this figure. This picture represents the physical pixel orientation, please note that output will have pixel 1 on top left to compensate for the lens by default as explained in section 7.20.





## 4.2. Pixel & Image Array Characteristics

| Parameter  | Min.        | Тур.           | Max.         | Unit     |
|--|-------------|----------------|--------------|----------|
| Pixel pitch                                      |             | 10             |              | μm       |
| Pixel architecture                               | Dual Tap Cu | rrent Assisted | Photonic Dem | odulator |
| External Quantum Efficiency <sup>1</sup> @ 850nm |             | 44.3           |              | %        |
| External Quantum Efficiency <sup>1</sup> @ 940nm |             | 25.5           |              | %        |
| Pixel dark noise                                 |             | 97             |              | e-       |
| AC demodulation contrast <sup>2</sup> @ 50MHz    |             | 85             |              | %        |
| AC demodulation contrast <sup>2</sup> @ 100MHz   |             | 69             |              | %        |
| Single tap dark current                          | 20          | 51             | 508          | ke-/s    |
| Single tap full well capacity                    | 106         | 160            |              | ke-      |
| Single tap conversion gain                       |             | 0.0106         |              | DN/e-    |
| Phase drift over temperature <sup>3</sup>        |             | 0.046          |              | deg/°C   |
| Local PDNU <sup>4</sup>                          |             |                | tbd          | deg      |
| Global PDNU <sup>5</sup>                         |             |                | tbd          | deg      |
| Defective pixel <sup>6</sup>                     |             |                | tbd          | pixel    |
| Microlense(s)                                    |             | Yes            |              |          |
| Maximum CRA (chief ray angle)                    |             |                | 30           | 0        |

Table 7: Pixel & Image Array Characteristics

 $\text{Note}^{\scriptscriptstyle 1} \colon \text{External quantum efficiency (EQE) can be calculated as } EQE_{\lambda} = \frac{\text{RE}_{\lambda}}{\lambda} \cdot \frac{h \cdot c}{e} \cdot FF = \frac{\text{RE}_{\lambda}}{\lambda} \cdot 1240 \cdot FF$ 

 $RE_{\mathbb{Z}}$  = responsivity at wavelength (in A/W)

c = speed of light in vacuum e = elemental charge

E - elementar charge

FF = fill factor (in %)

Note<sup>2</sup>: Detailed AC demodulation contrast data can be found in Figure 8.

Note<sup>3</sup>: Stability of the calculated phase (= distance) over temperature

Note4: Local PDNU (phase depth non uniformity) is a metric for the phase offset between 3x3 pixel blocks for a

homogeneous flat field measurement

Note<sup>5</sup> : Global PDNU is similar to local PDNU but data is based on 10x10 pixel blocks

Note<sup>6</sup>: A defective pixel is defined as a pixel with low demodulation contrast or low responsivity compared to its neighbours

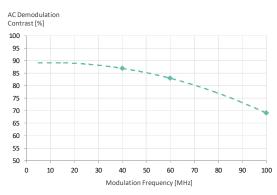


Figure 8 : AC Demodulation Contrast in function of Modulation Frequency

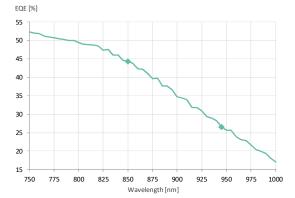


Figure 9: External Quantum Efficiency in function of Wavelength



# 4.3. CRA (Chief Ray Angle)

| Image Height <sup>1</sup><br>(%) | Image Height¹<br>(mm) | CRA (°) |
|----------------------------------|-----------------------|---------|
| 0                                | 0.0                   | 0       |
| 10                               | 0.4                   | 3.3     |
| 20                               | 0.8                   | 6.6     |
| 30                               | 1.2                   | 9.8     |
| 40                               | 1.6                   | 13      |
| 50                               | 2.0                   | 16.1    |
| 60                               | 2.4                   | 19.1    |
| 70                               | 2.8                   | 22.0    |
| 80                               | 3.2                   | 24.8    |
| 90                               | 3.6                   | 27.5    |
| 100                              | 4.0                   | 30      |

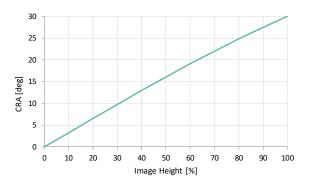


Table 8: Image Height vs CRA

Note<sup>1</sup>: Image height is defined along the diagonal axis of the image array as shown below.

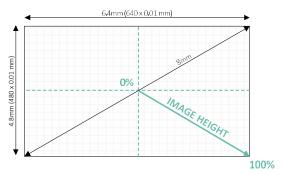


Figure 10 : Image Height Definition

# 4.4. Application Lens Design Recommendations

When designing or selecting external optics to focus the light on the optical sensitive pixel area there are a few recommendations to take into account:

- To avoid pixel saturation under strong sunlight an optical bandpass filter is highly recommended.
   The spectral width of this filter depends on the type of illumination, LED or VCSEL, and should be as small as possible, taken into account the spectral drift over temperature.
- To reduce the illumination radiant intensity and to maximize the system efficiency the lens aperture should be as high as possible (= low F-number)
- The built-in microlenses require UV protection, most conveniently integrated into the lens, to avoid permanent deformation of the optics. UV exposure must be limited to tbd over lifetime.



# 5. Communication Interface(s)

MLX75027 features two different communication methods. One low speed bidirectional I2C interface used for register control, and one unidirectional high speed MIPI CSI2 serial video output interface.

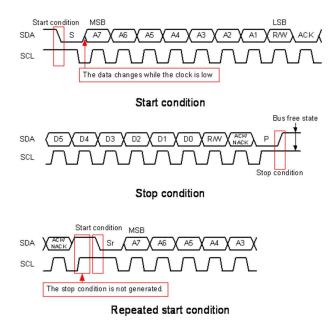
## 5.1. I<sup>2</sup>C (Inter-Integrated Circuit)

This 2-wire serial communication protocol supports 16 bit register addresses and 8 bit data messages.

## 5.1.1. I<sup>2</sup>C Timing Sequence

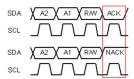


The data is transferred serially, MSB first in 8-bit units. After each data byte is transferred, A (Acknowledge) / A (Negative acknowledge) is transferred. Data (SDA) is transferred at the clock (SDL) cycle. SDA can change only while SCL is low, so the SDA value must be held while SCL is high. The Start condition is defined by SDA changing from high to low while SCL is high. When the Stop condition is not generated in the previous communication phase and Start condition for the next communication is generated, that Start condition is recognized as a Repeated Start condition.





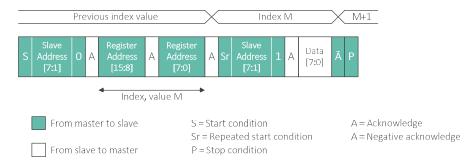
After transfer of each data byte, the Master or the sensor transmits an Acknowledge / Negative acknowledge and releases (does not drive) SDA. When Negative acknowledge is generated, the Master must immediately generate the Stop Condition and end the communication.



Acknowledge, Negative Acknowledge

## 5.1.2. Single I<sup>2</sup>C Read

The sensor has an index function that indicates which address it is focusing on. When reading data the Master must set the index value to the address to be read. For this purpose it performs a dummy write operation up to the register address. The upper level of the figure shows the sensor internal index value, and the lower level of the figure shows the SDA I/O data flow. The Master sets the sensor index value to M by designating the sensor slave address with a write request, then designating the address (M). Then, the Master generates the start condition. The Start Condition is generated without generating the Stop Condition, so it becomes the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge immediately followed by the address data from index M on SDA. After the Master receives the data, it generates a Negative Acknowledge and the Stop Condition to end the communication

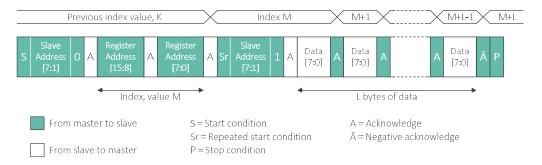


<u>Note</u>: It is possible to omit the Register Address [15:0] from the communication, in that case the sensor will simply read the value of register previously set to index M.



### 5.1.3. Sequential I<sup>2</sup>C Read

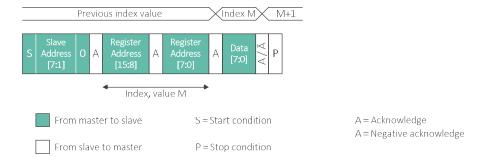
A sequential read of the data reads multiple registers sequentially without setting the register addresses individually. The Master must set the index value to the start of the addresses to be read. For this purpose, a dummy write operation includes the register address setting. The Master sets the sensor index value to M by designating the sensor slave address with a read request, then designating the address (M). Then, the Master generates the Repeated Start Condition. Next, when the Master sends the slave address with a read request, the sensor outputs an Acknowledge followed immediately by the data from index M on SDA. When the Master outputs an Acknowledge (instead of Negative acknowledge for a single I<sup>2</sup>C read) after it receives the data, the index value inside the sensor is incremented and the data at the next address is output on SDA. This allows the Master to read data sequentially. After reading the necessary data, the Master generates a Negative Acknowledge and the Stop Condition to end the communication.



<u>Note</u>: It is possible to omit the Register Address [15:0] from the communication, in that case the sensor will simply read the values of the registers starting at the previously set index M.

### 5.1.4. Single I<sup>2</sup>C Write

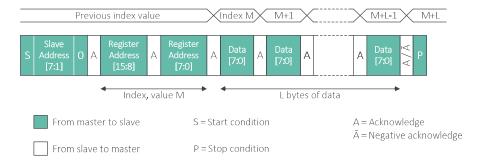
The Master sets the sensor index value to M by designating the sensor slave address with a write request, and designating the register address (M). After that the Master can write the value in the designated register by transmitting the data to be written. After writing the necessary data, the Master generates the Stop Condition to end the communication.





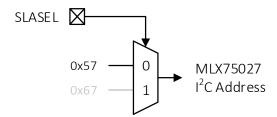
# 5.1.5. Sequential I<sup>2</sup>C Write

The Master can write a value to register address M by designating the sensor slave address with a write request, designating the address (M), and then transmitting the data to be written. After the sensor receives the write data, it outputs an Acknowledge and at the same time increments the register address, so the Master can write to the next address simply by continuing to transmit data. After the Master writes the necessary number of bytes, it generates the Stop Condition to end the communication.



### 5.1.6. I<sup>2</sup>C Slave Address

For communication with MLX75027 via I<sup>2</sup>C the user has to choose between two different 7bit slave addresses. Selection can be done by the external SLASEL pin, by connecting it either to VDDD (high) or DGND (low).



Important Note: I<sup>2</sup>C slave address 0x67 is not programmed on engineering samples. To avoid bring-up issues, please connect SLASEL to GND.

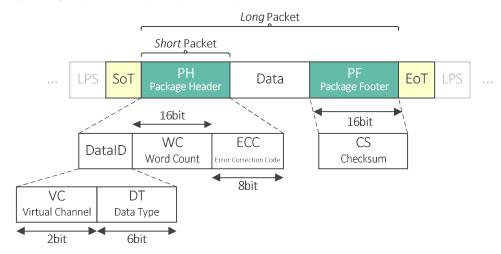


## 5.2. MIPI Alliance CSI-2 Description

This section describes a limited set of CSI-2 functionality needed to understand operation of MLX75027. For a full interface description, please refer to MIPI Alliance CSI-2 Specification version 1.20.

#### 5.2.1. Packet Structure

CSI-2 uses a byte oriented, packet based protocol that supports the transport of arbitrary data using *Short Package* (SP) and *Long Package* (LP) formats. A 32bit *Short Packet* does not have any data or a *Package Footer* (PF). Only FS (*Frame Start*) or FE (*Frame End*) indicators use *Short Packets*.



Every packet starts with a SoT (start of transmission) sequence preceded by a LPS (low power state). An EoT (end of transmission) sequence followed by the low power state indicates the end of a packet.

Each byte is transmitted with the least significant bit first, in case of multi-byte data (such as WC or CS) the least significant byte will be transmitted first, unless otherwise specified by the data format.

VC: The virtual channel identifier provides separate channels for different data flows that are interleaved in the data stream (lane indicator). The default value is 0.

DT: The data type value specifies the format and content of the data payload.

0x00 = FS (Frame Start) 0x12 = Embedded data (or MetaData)

0x01 = FE (Frame End) 0x2C = RAW12 pixel data

WC: For short packets the word count field is considered a 16bit data field, representing the Frame Count [7:0]. After each FS (Frame Start) transmission, the Frame Count will be increased by 1. For long packets word count specifies the total amount of bytes between the end of PH and start of PF.

ECC: The error correction code used is a 7+1bits Hamming-modified code. This code allows single-bit errors to be corrected and 2-bit errors to be detected in the DataID and WC fields but is not capable of doing both simultaneously.

CS: To detect possible errors in the data transmission, a checksum is calculated over each data packet. The checksum is a 16bit CRC generated by this polynomial:

$$CRC = x^{16} + x^{12} + x^5 + x^0$$

When WC is zero, CS will be 0xFFFF



#### 5.2.2. Data Format RAW12

Each DepthSense® pixel is represented by 12bit data packed like 8bit data.

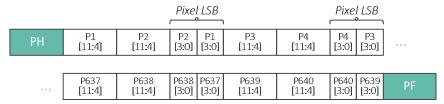


Figure 11: Example of pixel ordering for one full line transmission



Figure 12: Example of pixel ordering for one full frame transmission

Table 9 specifies the minimum packet data size constraints.

The total length of each packet must be a multiple of the values in this table.

| # Pixels | # Bytes | # Bits |
|----------|---------|--------|
| 2        | 3       | 24     |

Table 9: RAW12 Packet size constraints

#### 5.2.2.1. Data Format in 4 Lane MIPI Configuration



Figure 13: Pixel Data Format in 4 Lane Data Configuration

### 5.2.2.2. Data Format in 2 Lane MIPI Configuration

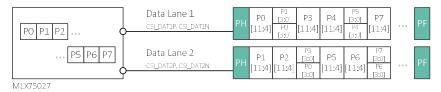


Figure 14 : Pixel Data Format in 2 Lane Data Configuration



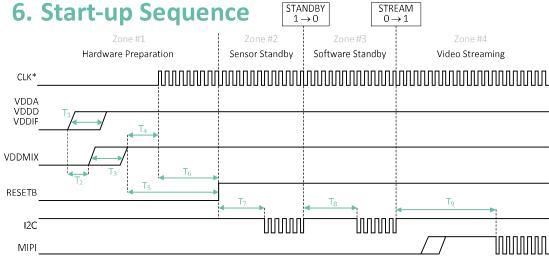


Figure 15: Sensor start-up sequence

<sup>\*</sup> Availability of CLK signal before voltage domain bring up is also accepted

| 0x1000       | 7      | 6 | 5 | 4 | 3 | 2 | 1 | 0       |
|--------------|--------|---|---|---|---|---|---|---------|
| R/W          | -      | - | - | - | - | - | - | STANDBY |
| Default Valu | e 0x01 |   |   |   |   |   |   |         |
| 0x1001       | 7      | 6 | 5 | 4 | 3 | 2 | 1 | 0       |
| R/W          | -      | - | - | - | - | - | - | STREAM  |

Default Value 0x00

Zone #1: Hardware Preparation: Time to supply the clock, the required voltage domains and initialize the

RESETB level. RESETB is a digital control signal, the  $\mu C$  keeps it low until all

requirements of zone 2 have been fulfilled.

Zone #2 : **Sensor Standby :** Time to define input clock settings, as shown in section 6.1

Zone #3: Software Standby: In this period it's advised to write all frame acquisition parameters (like

integration time, modulation frequency & others) before video streaming.

Zone #4 : Video Streaming : Frame capture is active and MIPI output data is available. Register changes

during active frame acquisition will be applied on the next frame.

| Description   | Symbol         | Min.            | Max.                   | Uni |
|---|----------------|-----------------|------------------------|-----|
| Time between VDDA OFF and VDDA ON Time between VDDD OFF and VDDD ON Time between VDDIF OFF and VDDIF ON | Т1             | 108<br>48<br>72 |                        | μs  |
| Time between VDDA, VDDD, VDDIF ON and VDDMIX ON   | T <sub>2</sub> | 0               |                        | μs  |
| Time between VDDMIX OFF and VDDMIX ON   | T <sub>3</sub> | 48              |                        | μs  |
| Time between VDDDMIX ON and CLK ON  | T <sub>4</sub> | 0               |                        | μs  |
| Time between VDDA, VDDD, VDDIF, VDDMIX, CLK ON and RESETB OFF   | T <sub>5</sub> | 100             |                        | μs  |
| Time between CLK ON and RESETB OFF  | T <sub>6</sub> | 0               |                        | μs  |
| Time between RESETB and first I <sup>2</sup> C command  | T <sub>7</sub> | 100             |                        | μs  |
| Time between STANDBY OFF and STREAM ON  | T <sub>8</sub> | 12              |                        | ms  |
| Time between STREAM ON and first video data   | T <sub>9</sub> |                 | 2.8 + T <sub>int</sub> | ms  |



# 6.1. Initialization Process

MLX75027 requires a SW initialization on each start-up/reset and/or power cycle.

| Operating Mode       | Register<br>Address   | Register<br>Value  | Comment   |  |
|----------------------|---|--------------------|---|--|
| Hardware Preparation |   |                    | End Hardware Preparation by pulling RESETB high   |  |
|                      | 0x1006  | 0x08               |   |  |
|                      | 0x1007  | 0x00               |   |  |
|                      | 0x1040  | 0x00               |   |  |
|                      | 0x1041  | 0x96               |   |  |
|                      | 0x1042  | 0x01               | Fixed Input Clock Settings  |  |
| Sensor Standby       | 0x1043  | 0x00               |   |  |
|                      | 0x1044  | 0x00               |   |  |
|                      | 0x1046  | 0x01               |   |  |
|                      | 0x104A  | 0x01               |   |  |
|                      | 0x1000  | 0x00               | Change from <i>Sensor Standby</i> to <i>Software Standby</i> by changing register 0x1000 (default value 0x01) to value 0x00 |  |
|                      |   | alization<br>sters | Program the FULL initialization map from section 6.2  |  |
|                      | Add here relevant application registers that require an update of their reset value |                    |   |  |
|                      | $\checkmark$  |                    | (examples listed below)   |  |
|                      | 0x100C  |                    |   |  |
|                      |   | custom             | Configure video output interface  |  |
|                      | 0x1071  |                    | (see section 7.1)   |  |
|                      | 0x2020  | custom             |   |  |
|                      | 0x2100  | custom             |   |  |
|                      | 0x2F05  | custom             | Configure TRIGGER or CONTINUOUS mode  |  |
|                      | 0x2F06  | custom             | (see section 7.2)   |  |
|                      | 0x2F07  | custom             |   |  |
|                      | 0x3071  | custom             |   |  |
|                      | 0x0828  | custom             | Configure Data Output Mode (see section 7.3)  |  |
| Software Standby     | 0x0800  | custom             | Configure HMAX (see section 7.4)  |  |
|                      | 0x0801  | custom             | comigare minut (see section 7.1)  |  |
|                      | 0x21BE  |                    | Configure Modulation Frequency  |  |
|                      |   | custom             | (see section 7.7)   |  |
|                      | 0x104B  |                    |   |  |
|                      | 0x21E8  | custom             | Configure number of phases (see section 7.11)   |  |
|                      | 0x2120  | custom             | Configure Integration Time per phase  |  |
|                      | <br>0x213F  | custom             | (see section 0)   |  |
|                      | 0x2131  |                    |   |  |
|                      |   | custom             | Configure PHASE_SHIFT per phase   |  |
|                      | 0x21B7  | 04010111           | (see section 7.14)  |  |
|                      | A   |                    | End of relevant application registers   |  |
|                      | 0x1001  | 0x01               | Enter <i>Video Streaming</i> by changing register 0x1001 (value 0x00) to value 0x01   |  |
| Video Streaming      |   |                    | Application is now running  |  |



# 6.2. Initialization Register Map

This set of initialization registers are listed in order or priority (top > bottom, left > right, next page):

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x10D2   | 0x00     |
| 0x10D3   | 0x10     |
| 0x1448   | 0x06     |
| 0x1449   | 0x40     |
| 0x144A   | 0x06     |
| 0x144B   | 0x40     |
| 0x144C   | 0x06     |
| 0x144D   | 0x40     |
| 0x144E   | 0x06     |
| 0x144F   | 0x40     |
| 0x1450   | 0x06     |
| 0x1451   | 0x40     |
| 0x1452   | 0x06     |
| 0x1453   | 0x40     |
| 0x1454   | 0x06     |
| 0x1455   | 0x40     |
| 0x1456   | 0x06     |
| 0x1457   | 0x40     |
| 0x21C4   | 0x00     |
| 0x2202   | 0x00     |
| 0x2203   | 0x1E     |
| 0x2C08   | 0x01     |
| 0x2C0C   | 0x51     |
| 0x2C0D   | 0x00     |
| 0x3C2B   | 0x1B     |
| 0x400E   | 0x01     |
| 0x400F   | 0x81     |
| 0x40D1   | 0x00     |
| 0x40D2   | 0x00     |
| 0x40D3   | 0x00     |
| 0x40DB   | 0x3F     |
| 0x40DE   | 0x40     |
| 0x40DF   | 0x01     |
| 0x412C   | 0x00     |
| 0x4134   | 0x04     |
| 0x4135   | 0x04     |
| 0x4136   | 0x04     |
| 0x4137   | 0x04     |
| 0x4138   | 0x04     |
| 0x4139   | 0x04     |
| 0x413A   | 0x04     |
| 0x413B   | 0x04     |

| Register<br>Address | Register<br>Value |
|---------------------|-------------------|
| 0x413C              | 0x04              |
| 0x4146              | 0x01              |
| 0x4147              | 0x01              |
| 0x4148              | 0x01              |
| 0x4149              | 0x01              |
| 0x414A              | 0x01              |
| 0x414B              | 0x01              |
| 0x414C              | 0x01              |
| 0x414D              | 0x01              |
| 0x4158              | 0x01              |
| 0x4159              | 0x01              |
| 0x415A              | 0x01              |
| 0x415B              | 0x01              |
| 0x415C              | 0x01              |
| 0x415D              | 0x01              |
| 0x415E              | 0x01              |
| 0x415F              | 0x01              |
| 0x4590              | 0x00              |
| 0x4591              | 0x2E              |
| 0x4684              | 0x00              |
| 0x4685              | 0xA0              |
| 0x4686              | 0x00              |
| 0x4687              | 0xA1              |
| 0x471E              | 0x07              |
| 0x471F              | 0xC9              |
| 0x473A              | 0x07              |
| 0x473B              | 0xC9              |
| 0x4770              | 0x00              |
| 0x4771              | 0x00              |
| 0x4772              | 0x1F              |
| 0x4773              | 0xFF              |
| 0x4778              | 0x06              |
| 0x4779              | 0xA4              |
| 0x477A              | 0x07              |
| 0x477B              | 0xAE              |
| 0x477D              | 0xD6              |
| 0x4788              | 0x06              |
| 0x4789              | 0xA4              |
| 0x478C              | 0x1F              |
| 0x478D              | OxFF              |
| 0x478E              | 0x00              |

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x478F   | 0x00     |
| 0x4792   | 0x00     |
| 0x4793   | 0x00     |
| 0x4796   | 0x00     |
| 0x4797   | 0x00     |
| 0x479A   | 0x00     |
| 0x479B   | 0x00     |
| 0x479C   | 0x1F     |
| 0x479D   | 0xFF     |
| 0x479E   | 0x00     |
| 0x479F   | 0x00     |
| 0x47A2   | 0x00     |
| 0x47A3   | 0x00     |
| 0x47A6   | 0x00     |
| 0x47A7   | 0x00     |
| 0x47AA   | 0x00     |
| 0x47AB   | 0x00     |
| 0x47AC   | 0x1F     |
| 0x47AD   | 0xFF     |
| 0x47AE   | 0x00     |
| 0x47AF   | 0x00     |
| 0x47B2   | 0x00     |
| 0x47B3   | 0x00     |
| 0x47B6   | 0x00     |
| 0x47B7   | 0x00     |
| 0x47BA   | 0x00     |
| 0x47BB   | 0x00     |
| 0x47BC   | 0x1F     |
| 0x47BD   | 0xFF     |
| 0x47BE   | 0x00     |
| 0x47BF   | 0x00     |
| 0x47C2   | 0x00     |
| 0x47C3   | 0x00     |
| 0x47C6   | 0x00     |
| 0x47C7   | 0x00     |
| 0x47CA   | 0x00     |
| 0x47CB   | 0x00     |
| 0x4834   | 0x00     |
| 0x4835   | 0xA0     |
| 0x4836   | 0x00     |
| 0x4837   | 0xA1     |

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x4878   | 0x00     |
| 0x4879   | 0xA0     |
| 0x487A   | 0x00     |
| 0x487B   | 0xA1     |
| 0x48BC   | 0x00     |
| 0x48BD   | 0xA0     |
| 0x48BE   | 0x00     |
| 0x48BF   | 0xA1     |
| 0x4954   | 0x00     |
| 0x4955   | 0xA0     |
| 0x4956   | 0x00     |
| 0x4957   | 0xA1     |
| 0x4984   | 0x00     |
| 0x4985   | 0xA0     |
| 0x4986   | 0x00     |
| 0x4987   | 0xA1     |
| 0x49B8   | 0x00     |
| 0x49B9   | 0x78     |
| 0x49C2   | 0x00     |
| 0x49C3   | 0x3C     |
| 0x49C8   | 0x00     |
| 0x49C9   | 0x76     |
| 0x49D2   | 0x00     |
| 0x49D3   | 0x3F     |
| 0x49DC   | 0x00     |
| 0x49DD   | 0xA0     |
| 0x49DE   | 0x00     |
| 0x49DF   | 0xA1     |
| 0x49EE   | 0x00     |
| 0x49EF   | 0x78     |
| 0x49F8   | 0x00     |
| 0x49F9   | 0x3C     |
| 0x49FE   | 0x00     |
| 0x49FF   | 0x78     |
| 0x4A04   | 0x00     |
| 0x4A05   | 0x3C     |
| 0x4A0A   | 0x00     |
| 0x4A0B   | 0x76     |
| 0x4A10   | 0x00     |
| 0x4A11   | 0x3F     |
| 0x4A1A   | 0x00     |

Table 10 : Initialization Map Part I

### MLX75027 VGA Time-of-Flight Sensor

PRELIMINARY DATASHEET



| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x4A1B   | 0xA0     |
| 0x4A1C   | 0x00     |
| 0x4A1D   | 0xA1     |
| 0x4A1E   | 0x00     |
| 0x4A1F   | 0x78     |
| 0x4A28   | 0x00     |
| 0x4A29   | 0x3C     |
| 0x4A4A   | 0x00     |
| 0x4A4B   | 0xA0     |
| 0x4A4C   | 0x00     |
| 0x4A4D   | 0xA1     |
| 0x4A7A   | 0x00     |
| 0x4A7B   | 0xA0     |
| 0x4A7C   | 0x00     |
| 0x4A7D   | 0xA1     |
| 0x4AEE   | 0x00     |
| 0x4AEF   | 0xA0     |
| 0x4AF0   | 0x00     |
| 0x4AF1   | 0xA1     |
| 0x4B2E   | 0x00     |
| 0x4B2F   | 0xA0     |
| 0x4B30   | 0x00     |
| 0x4B31   | 0xA1     |
| 0x4B5A   | 0x00     |
| 0x4B5B   | 0xA0     |
| 0x4B5C   | 0x00     |
| 0x4B5D   | 0xA1     |
| 0x4B86   | 0x00     |
| 0x4B87   | 0xA0     |
| 0x4B88   | 0x00     |
| 0x4B89   | 0xA1     |
| 0x4B9E   | 0x00     |
| 0x4B9F   | 0x1A     |
| 0x4BAE   | 0x00     |
| 0x4BAF   | 0x1A     |
| 0x4BB6   | 0x00     |

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x4BC6   | 0x00     |
| 0x4BC7   | 0x1A     |
| 0x4BCE   | 0x00     |
| 0x4BCF   | 0x1A     |
| 0x4BEE   | 0x00     |
| 0x4BEF   | 0xA0     |
| 0x4BF0   | 0x00     |
| 0x4BF1   | 0xA1     |
| 0x4BF6   | 0x00     |
| 0x4BF7   | 0x1A     |
| 0x4C00   | 0x00     |
| 0x4C01   | 0x1A     |
| 0x4C58   | 0x00     |
| 0x4C59   | 0xA0     |
| 0x4C5A   | 0x00     |
| 0x4C5B   | 0xA1     |
| 0x4C6E   | 0x00     |
| 0x4C6F   | 0xA0     |
| 0x4C70   | 0x00     |
| 0x4C71   | 0xA1     |
| 0x4C7A   | 0x01     |
| 0x4C7B   | 0x35     |
| 0x4CF2   | 0x07     |
| 0x4CF3   | 0xC9     |
| 0x4CF8   | 0x06     |
| 0x4CF9   | 0x9B     |
| 0x4CFA   | 0x07     |
| 0x4CFB   | 0xAE     |
| 0x4CFE   | 0x07     |
| 0x4CFF   | 0xC9     |
| 0x4D04   | 0x06     |
| 0x4D05   | 0x98     |
| 0x4D06   | 0x07     |
| 0x4D07   | 0xB1     |
| 0x4D18   | 0x06     |
| 0x4D19   | 0xA4     |
|          |          |

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x4D1B   | 0x49     |
| 0x4D1E   | 0x07     |
| 0x4D1F   | 0xC9     |
| 0x4D2A   | 0x07     |
| 0x4D2B   | 0xC9     |
| 0x4D4A   | 0x07     |
| 0x4D4B   | 0xC9     |
| 0x4D50   | 0x06     |
| 0x4D51   | 0x9B     |
| 0x4D52   | 0x07     |
| 0x4D53   | 0xAE     |
| 0x4D56   | 0x07     |
| 0x4D57   | 0xC9     |
| 0x4D5C   | 0x06     |
| 0x4D5D   | 0x98     |
| 0x4D5E   | 0x07     |
| 0x4D5F   | 0xB1     |
| 0x4D70   | 0x06     |
| 0x4D71   | 0xA4     |
| 0x4D72   | 0x07     |
| 0x4D73   | 0x49     |
| 0x4D78   | 0x06     |
| 0x4D79   | 0xA4     |
| 0x4D7A   | 0x07     |
| 0x4D7B   | 0xAE     |
| 0x4D7C   | 0x1F     |
| 0x4D7D   | 0xFF     |
| 0x4D7E   | 0x1F     |
| 0x4D7F   | 0xFF     |
| 0x4D80   | 0x06     |
| 0x4D81   | 0xA4     |
| 0x4D82   | 0x07     |
| 0x4D83   | 0xAE     |
| 0x4D84   | 0x1F     |
| 0x4D85   | 0xFF     |
| 0x4D86   | 0x1F     |
| 0x4D87   | 0xFF     |

| Register | Register |
|----------|----------|
| Address  | Value    |
| 0x4E39   | 0x07     |
| 0x4E7B   | 0x64     |
| 0x4E8E   | 0x0E     |
| 0x4E9A   | 0x00     |
| 0x4E9C   | 0x01     |
| 0x4EA0   | 0x01     |
| 0x4EA1   | 0x03     |
| 0x4EA5   | 0x00     |
| 0x4EA7   | 0x00     |
| 0x4F05   | 0x04     |
| 0x4F0D   | 0x04     |
| 0x4F15   | 0x04     |
| 0x4F19   | 0x01     |
| 0x4F20   | 0x01     |
| 0x4F66   | 0x0F     |
| 0x500F   | 0x01     |
| 0x5224   | 0x00     |
| 0x5225   | 0x2F     |
| 0x5226   | 0x00     |
| 0x5227   | 0x1E     |
| 0x5230   | 0x00     |
| 0x5231   | 0x19     |
| 0x5244   | 0x00     |
| 0x5245   | 0x07     |
| 0x5252   | 0x07     |
| 0x5253   | 0x08     |
| 0x5254   | 0x07     |
| 0x5255   | 0xB4     |
| 0x5271   | 0x00     |
| 0x5272   | 0x04     |
| 0x5273   | 0x2E     |
| 0x5281   | 0x00     |
| 0x5282   | 0x04     |
| 0x5283   | 0x2E     |
| 0x5285   | 0x00     |
| 0x5286   | 0x00     |

0x5287

0x5D

Table 11 : Initialization Map Part II

0x4D1A

0x07

0x4BB7



# 7. Register Settings

# 7.1. Video Output Configuration

Correct data communication settings have to be programmed in *Software Standby* mode. This is part of the initialization map as described in section 6.

| 0x1010 | 7 | 6 | 5 | 4 | 3 | 2 | 1                | 0 |
|--------|---|---|---|---|---|---|------------------|---|
| R/W    | - | - | - | - | - | - | DATA_LANE_CONFIG | 1 |

Reset Value 0x03

- 1b0: 2 data lane configuration
- 1b1: 4 data lane configuration (= default)

Registers listed in Table 12 need to be updated to support data transmission speeds of 300, 600, 704, 800 & 960 Mbps.

| # Data<br>Lanes | Communication<br>Speed | 0x100C | 0x100D | 0x1016 | 0x1017 | 0x1045 | 0x1047 | 0x1060 | 0x1071 |
|-----------------|------------------------|--------|--------|--------|--------|--------|--------|--------|--------|
|                 | 300 Mbps               | 0x02   | 0x58   | 0x09   | 0x99   | 0x4B   | 0x02   | 0x01   | 0x0C   |
|                 | 600 Mbps               | 0x04   | 0xB0   | 0x04   | 0xCC   | 0x4B   | 0x02   | 0x00   | 0x06   |
| 2               | 704 Mbps               | 0x05   | 0x80   | 0x04   | 0x17   | 0x58   | 0x02   | 0x00   | 0x06   |
|                 | 800 Mbps               | 0x06   | 0x40   | 0x03   | 0x99   | 0x64   | 0x02   | 0x00   | 0x06   |
|                 | 960 Mbps               | 0x07   | 0x80   | 0x03   | 0x00   | 0x78   | 0x02   | 0x00   | 0x06   |
|                 | 300 Mbps               | 0x04   | 0xB0   | 0x09   | 0x99   | 0x4B   | 0x02   | 0x01   | 0x0C   |
|                 | 600 Mbps               | 0x09   | 0x60   | 0x04   | 0xCC   | 0x4B   | 0x02   | 0x00   | 0x06   |
| 4               | 704 Mbps               | 0x0B   | 0x00   | 0x04   | 0x17   | 0x58   | 0x02   | 0x00   | 0x06   |
|                 | 800 Mbps               | 0x0C   | 0x80   | 0x03   | 0x99   | 0x64   | 0x02   | 0x00   | 0x06   |
|                 | 960 Mbps               | 0x0F   | 0x00   | 0x03   | 0x00   | 0x78   | 0x00   | 0x00   | 0x06   |

Table 12: Data Rate Configuration Settings

| 0x1C40 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0       |
|--------|---|---|---|---|---|---|---|---------|
| R/W    | - | - | - | - | - | - | - | CLK_OFF |

Reset Value 0x01

The clock enters a low power state (LPS) between the different data frames (CLK\_OFF=1) by default. It is possible to enable to clock continuously (stay in HS mode during frame blanking) via parameter CLK\_OFF=0 for compatibility with some microcontrollers.

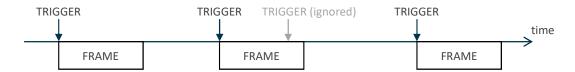


# 7.2. Modes of Operation

MLX75027 features two modes of operation: triggered or continuous mode. It's mandatory to change the operating mode during *Software Standby* as described in section 6.

| Register<br>Address |   | Register Value   |  |  |  |  |  |  |  |  |
|---------------------|---|--|--|--|--|--|--|--|--|--|
|                     | TRIGGERED MODE<br>(by external pin K11) | CONTINUOUS MODE  |  |  |  |  |  |  |  |  |
| 0x2020              | 0x00                                    | 0x01   |  |  |  |  |  |  |  |  |
| 0x2100              | 0x00                                    | Ox08 (internal triggers at FRAME_TIME interval, section 7.10) Ox01 (= self-clearing bit[0] that can be used as SW trigger via I2C on each frame) |  |  |  |  |  |  |  |  |
| 0x2F05              | 0x07                                    | 0x01   |  |  |  |  |  |  |  |  |
| 0x2F06              | 0x00                                    | 0x09   |  |  |  |  |  |  |  |  |
| 0x2F07              | 0x00                                    | 0x7A   |  |  |  |  |  |  |  |  |
| 0x3071              | 0x03                                    | 0x00   |  |  |  |  |  |  |  |  |

In triggered mode the TRIGGER pin accepts active low pulses to start a new frame. External (or internal) pulses send during an active frame acquisition will be ignored as indicated here:





### 7.3. Data Output Modes

One Depthsense® pixel has two outputs, known as tap A and tap B, each in counterphase (180° shifted) of one another. To reduce the calculation time from raw data to distance information MLX75027 supports output modes that already combine the information from both taps, either as sum or as difference.

For Time-of-Flight experts the raw information of both taps is also available either in Raw A, Raw B or Raw A & B output modes. Regular users should use the default output mode A-B since this directly reduces the required processing power to calculate the distance map on the microcontroller. More information on the distance calculation is available section 9.

The data output mode cannot change during *video streaming*, it is mandatory to change the data output mode during *Software Standby* as described in section 6.

| 0x0828 | 7 | 6 | 5 | 4 | 3 | 2 | 1           | 0 |
|--------|---|---|---|---|---|---|-------------|---|
| R/W    | - | - | - | - | - |   | OUTPUT_MODE |   |

Reset Value 0x00

- 3b000: Mode A-B (=12bit signed data)
- 3b001: Mode A+B (=12bit unsigned data)
- 3b010: Mode Raw A3b011: Mode Raw B
- 3b100: Mode Raw A & B

(other values are prohibited)

A full VGA frame in Mode A-B looks like Figure 16. The default horizontal resolution is 640 pixels, except in Mode Raw & B where two values per pixel (=1280) will be read out.

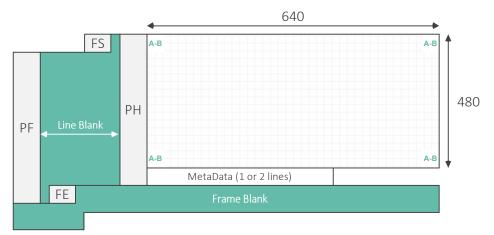


Figure 16: A single MIPI Frame



### 7.4. HMAX & Frame Read-Out Time

The HMAX parameter represents a number of internal clock pulses needed for one data row transmission. This time includes the communication protocol overhead (like data headers and power stage transitions), but also the actual data payload. It is a fixed value dependent on the data output configuration (section 7.1) and the output mode (section 7.3), it cannot be modified during *video streaming*. Other configuration parameters, expressed in function of HMAX, need to be modified accordingly. (see section 7.4.1, 7.4.2 and 7.4.3)

| 0x0800      | 7                     | 6 | 5           | 4 | 3 | 2 | 1 | 0 |  |  |
|-------------|-----------------------|---|-------------|---|---|---|---|---|--|--|
| R/W         | -                     | - | HMAX [13:8] |   |   |   |   |   |  |  |
| Reset Value | 0x02                  |   |             |   |   |   |   |   |  |  |
|             |                       |   |             |   |   |   |   |   |  |  |
| 0x0801      | 7                     | 6 | 5           | 4 | 3 | 2 | 1 | 0 |  |  |
| R/W         | R/W <b>HMAX [7:0]</b> |   |             |   |   |   |   |   |  |  |

Reset Value 0xB6

The time needed to read out a single phase is highly linked with the HMAX parameter, the corresponding read out time can be found in the table below.

| Operation<br>Mode | DATA_LANE_CONFIG | Communication<br>Speed (Mbps) | НМАХ   | Single Phase<br>Readout Time <sup>1</sup> (ms) |
|-------------------|------------------|-------------------------------|--------|--|
|                   |                  | 300                           | 0x0E60 | 8.16   |
|                   |                  | 600                           | 0x0744 | 4.12   |
|                   | 2                | 704                           | 0x0636 | 3.52   |
| Mode A-B          |                  | 800                           | 0x057A | 3.11   |
| Mode A+B          |                  | 960                           | 0x0514 | 2.88   |
| Mode Raw A        |                  | 300                           | 0x0860 | 4.75   |
| Mode Raw B        |                  | 600                           | 0x0444 | 2.42   |
|                   | 4                | 704                           | 0x03A8 | 2.07   |
|                   |                  | 800                           | 0x033A | 1.83   |
|                   |                  | 960                           | 0x02B6 | 1.54   |
|                   |                  | 300                           | 0x1CC0 | 16.31  |
|                   |                  | 600                           | 0x0E88 | 8.25   |
|                   | 2                | 704                           | 0x0C6C | 7.05   |
|                   |                  | 800                           | 0x0AF4 | 6.22   |
| Ma-da Da A 0 D    |                  | 960                           | 0x0A28 | 5.76   |
| Mode Raw A&B      |                  | 300                           | 0x0E60 | 8.16   |
|                   |                  | 600                           | 0x0744 | 4.12   |
|                   | 4                | 704                           | 0x0636 | 3.52   |
|                   |                  | 800                           | 0x057A | 3.11   |
|                   |                  | 960                           | 0x0514 | 2.88   |

Note<sup>1</sup>: Continuous wave time of flight typically uses 4 phases/quads to calculate a single distance image. These four snapshots are taken sequentially in time, which leads to the fact that any time delay between these images can contribute to motion blur, depending on the speed of the detected object. The time between the images is dominated by the sensor read out time. In order to minimize motion artefacts the read out time should be chosen as short as possible. The time listed in this table are maximum values (in millisecond) for a single phase at full resolution (640x480 pixels). Reducing the image size (with ROI or binning) has a direct and positive impact on the read out time.

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PRELIMINARY DATASHEET



<u>Important</u>: Different timing related registers are closely linked to the HMAX parameter. It's the user responsibility to update PLLSETUP, PIXRST & RANDNMO each time HMAX value is adjusted.

### 7.4.1. PLLSSETUP

| 0x4010 | 7        | 6 | 5 | 4 | 3 | 2 | 1 | 0 |  |  |
|--------|----------|---|---|---|---|---|---|---|--|--|
| R/W    | PLLSETUP |   |   |   |   |   |   |   |  |  |
|        |          |   |   |   |   |   |   |   |  |  |

Reset Value 0x5F

PLLSETUP is the time required for the *Timing Generator* block (see section 2) to settle before each frame and it can be calculated as ROUNDUP  $\left(\frac{503 \cdot 120}{HMAX} + 8; 0\right)$ 

#### 7.4.2. PIXRST

| 7                | 6 | 5    | 4    | 3               | 2                 | 1                                   | 0                                |  |  |  |  |
|------------------|---|------|------|-----------------|-------------------|-------------------------------------|----------------------------------|--|--|--|--|
| -                | - | -    |      | I               | PIXRST [12:8]     | ]                                   |                                  |  |  |  |  |
| Reset Value 0x00 |   |      |      |                 |                   |                                     |                                  |  |  |  |  |
|                  |   |      |      |                 |                   |                                     |                                  |  |  |  |  |
| 7                | 6 | 5    | 4    | 3               | 2                 | 1                                   | 0                                |  |  |  |  |
| /W PIXRST [7:0]  |   |      |      |                 |                   |                                     |                                  |  |  |  |  |
|                  |   | 0x00 | Ox00 | Ox00<br>7 6 5 4 | 0x00<br>7 6 5 4 3 | PIXRST [12:8<br>0x00<br>7 6 5 4 3 2 | PIXRST [12:8] 0x00 7 6 5 4 3 2 1 |  |  |  |  |

Reset Value 0x0A

PIXRST is the pixel reset time before each integration time. It can be calculated as  $ROUNDUP\left(\frac{50 \cdot 120}{HMAX}; 0\right)$ 

#### 7.4.3. RANDNMO

| 0x5265           | 7              | 6 | 5               | 4 | 3 | 2 | 1 | 0 |  |  |  |
|------------------|----------------|---|-----------------|---|---|---|---|---|--|--|--|
| R/W              | -              | - | RANDNM0 [21:16] |   |   |   |   |   |  |  |  |
| Reset Value 0x00 |                |   |                 |   |   |   |   |   |  |  |  |
|                  |                |   |                 |   |   |   |   |   |  |  |  |
| 0x5266           | 7              | 6 | 5               | 4 | 3 | 2 | 1 | 0 |  |  |  |
| R/W              | RANDNM0 [15:8] |   |                 |   |   |   |   |   |  |  |  |
| Reset Value      | 0x1F           |   |                 |   |   |   |   |   |  |  |  |
|                  |                |   |                 |   |   |   |   |   |  |  |  |
| 0x5267           | 7              | 6 | 5               | 4 | 3 | 2 | 1 | 0 |  |  |  |
| R/W              | RANDNM0 [7:0]  |   |                 |   |   |   |   |   |  |  |  |

Reset Value 0x2C

RANDNM0 can be calculated as HMAX  $\cdot$  PIXRST - RANDNM7 - 2098 (RANDNM7 = 1070 with premix disabled, more information can be found in section 7.12)

PRELIMINARY DATASHEET



### 7.5. PARAM\_HOLD

Each frame consists of multiple configuration parameters, controlled via a *slow* I<sup>2</sup>C interface. To avoid frame to frame data corruption when changing more than one parameter (like to modulation frequency or integration time) the user can enable *shadow* registers that temporarily store the updated values and apply all changes at once when the PARAM\_HOLD bit is released.

| 0x0102 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0          |
|--------|---|---|---|---|---|---|---|------------|
| R/W    | - | - | - | - | - | - | - | PARAM_HOLD |

Reset Value 0x00

- 1b0: disable the shadow registers and update all registers at next TRIGGER pulse
- 1b1: enable the shadow registers

It is strongly recommended to use PARAM\_HOLD for any register changes during video streaming.

## 7.6. USER\_ID Register

A user programmable register, address 0x0824, will be read out in the first metadata line. This register, for example, can be used as an identifier for customer defined register maps. It is the user responsibility to program the USER\_ID register, together with other register changes, during a single PARAM\_HOLD period and after each phase it can be traced back which settings were used.

| 0x0824 | 7 | 6 | 5 | 4   | 3    | 2 | 1 | 0 |
|--------|---|---|---|-----|------|---|---|---|
| R/W    |   |   |   | USE | R_ID |   |   |   |

Reset Value 0x00



## 7.7. Modulation Frequency

The modulation frequency can be set for each frame between 4 and 100 MHz in steps of 1 MHz. Changing this frequency is possible during data streaming by changing the registers listed below. When updating the modulation frequency it's advised to use PARAM\_HOLD like explained in section 0.

Changing the modulation frequency requires a set of five register values to be updated consecutively.

|                     |     |           | Modulation Frequency                       |   |           |       |  |  |
|---------------------|-----|-----------|--|---|-----------|-------|--|--|
| Register<br>Address |     |           | [100-75] MHz<br>[50-38] MHz<br>[20-19] MHz | [74-51] MHz<br>[37-21] MHz<br>[18-10] MHz | [9-5] MHz | 4 MHz |  |  |
| 0x21BE              | R/W | DIVSELPRE | 0x00                                       | 0x01                                      | 0x02      | 0x03  |  |  |

|                     |     |        | Modu         | ulation Frequency |            |
|---------------------|-----|--------|--------------|-------------------|------------|
| Register<br>Address |     |        | [100-51] MHz | [50-21] MHz       | [20-4] MHz |
| 0x21BF              | R/W | DIVSEL | 0x00         | 0x01              | 0x02       |

| 0x1048      | 7    | 6 | 5 | 4    | 3     | 2 | 1           | 0        |
|-------------|------|---|---|------|-------|---|-------------|----------|
| R/W         | -    | - | - | -    | -     |   | FMOD [10:8] |          |
| Reset Value | 0x00 |   |   |      |       |   |             | <u> </u> |
| 0x1049      | 7    | 6 | 5 | 4    | 3     | 2 | 1           | 0        |
| R/W         |      |   |   | FMOD | [7:0] |   |             |          |

Reset Value 0x50

FMOD[10:0] value is calculated as 2 DIVSELPRE+DIVSEL · Modulation Frequency

#### Example FMOD values:

- Modulation Frequency 100 MHz ➤ FMOD = 100 = 0x64
- Modulation Frequency 80 MHz > FMOD = 80 = 0x50
- Modulation Frequency 40 MHz > FMOD = 80 = 0x50
- Modulation Frequency 20 MHz > FMOD = 80 = 0x50

| Register<br>Address |     | 500 ≤ FMOD · 8 < 900 | $900 \le \text{FMOD} \cdot 8 \le 1200$ |
|---------------------|-----|----------------------|--|
| 0x104B              | R/W | 0x02                 | 0x00                                   |



### 7.8. Frame Structure & Frame Rate

To reconstruct a 3D point cloud or a distance image based on indirect Time of Flight technology the sensor usually captures the phase interval for at least four sequential measurements, each called a phase. Each frame (or distance frame) can have up to eight individual phases configured (see section 7.11).

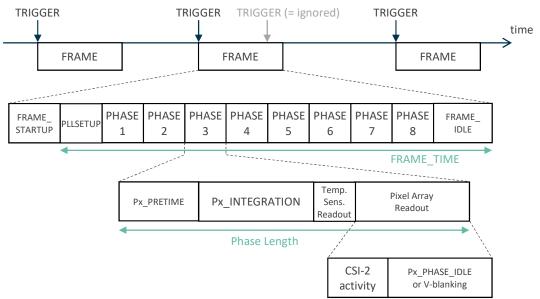


Figure 17: Frame Structure

In continuous operating mode the system frame rate can be calculated as  $\frac{1\,000\,000}{\text{Frame length (in }\mu\text{s})}$ 

Frame length (in 
$$\mu$$
s) =  $\frac{\text{FRAME\_STARTUP} \cdot \text{HMAX}}{120} + 500 + \text{FRAME\_TIME}$  (in  $\mu$ s) (eq.1)

• FRAME\_TIME (in 
$$\mu$$
s) = PHASE\_COUNT · Phase length (in  $\mu$ s) (eq.2)

or

FRAME\_TIME (in 
$$\mu$$
s) =  $\frac{FRAME\_TIME \cdot HMAX}{120}$  (only if an optional wait time is defined)

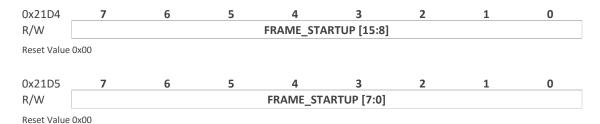
Phase length (in 
$$\mu$$
s) = 
$$\frac{(Px_PRETIME + 266 + Px_PHASE\_IDLE + Px_INTEGRATION) \cdot HMAX}{120}$$
 (eq.3)

In triggered mode the frame rate is controlled by the microcontroller.



### 7.9. FRAME\_STARTUP

The frame start up time is the time between a TRIGGER pulse and the start of the first phase acquisition. It can be used to synchronize multiple TOF systems and avoid optical interference.



The register value can be calculated as  $\frac{\text{start up time (in } \mu s) \cdot 120}{\dots}$ 

## 7.10. FRAME\_TIME

The minimum length of a frame is dominated by the individual phase configurations. Programming a FRAME\_TIME longer than the minimum time needed to capture all phases adds an additional wait time. This is convenient to achieve a fixed distance frame rate in continuous operating mode.

| Register Address |     | Register Name      | Default Value |
|------------------|-----|--------------------|---------------|
| 0x2108           | R/W | FRAME_TIME [31:24] | 0x00          |
| 0x2109           | R/W | FRAME_TIME [23:16] | 0x00          |
| 0x210A           | R/W | FRAME_TIME [15:8]  | 0x00          |
| 0x210B           | R/W | FRAME_TIME [7:0]   | 0x00          |

The register value can be calculated as  $\frac{\text{Frame Time (in } \mu s) \cdot 120}{\text{HMAX}}$ 

# 7.11. PHASE\_COUNT

It is possible to define up to eight raw phases in a single frame for more complex acquisition schemes. The amount of phases inside a frame has to be programmed into PHASE\_COUNT.

| 0x21E8 | 7 | 6 | 5 | 4 | 3 | 2      | 1     | 0 |
|--------|---|---|---|---|---|--------|-------|---|
| R/W    | - | - | - | - |   | PHASE_ | COUNT |   |

Reset Value 0x04

- 4b0001: Phase 1 enabled
- 4b0010: Phase 1 2 enabled
- 4b0011: Phase 1 3 enabled
- 4b0100: Phase 1 4 enabled
- 4b0101: Phase 1 5 enabled
- 4b0110: Phase 1 6 enabled
- 4b0111: Phase 1 7 enabled
- 4b1000: Phase 1 8 enabled

(other values are prohibited)



## 7.12. Px\_PREHEAT, Px\_PREMIX & Px\_PRETIME

It is important that the illumination signal per phase is constant because any inconsistency across the different raw phases will lead to a distance measurement error. Spikes, visible in the optical illumination signal, due to temperature effects in the first microseconds of an integration period can cause such non constant behaviour. This can be avoided by preheating the illumination signal per phase, known as Px\_PREHEAT and it can be enabled/disabled for each of the phases individually.

| 0x21C0 | 7       | 6       | 5       | 4       | 3       | 2       | 1       | 0       |
|--------|---------|---------|---------|---------|---------|---------|---------|---------|
| D /\/  | P8_     | P7_     | P6_     | P5_     | P4_     | P3_     | P2_     | P1_     |
| R/W    | PREHEAT |

Reset Value 0x00

1b0: preheat off1b1: preheat on

Although the measurement error is small on application level, similar effects can arise from the pixel/sensor side, for that reason it is also possible to enable a Px\_PREMIX time. This is the time the sensor will start integrating before the illumination control signal is enabled. Please note that during this time light will already be accumulated which can lead to a faster pixel saturation during integration time. It is advised to keep Px\_PREMIX disabled.

| 0x21C2 | 7      | 6      | 5      | 4      | 3      | 2      | 1      | 0      |
|--------|--------|--------|--------|--------|--------|--------|--------|--------|
| D /\A/ | P8_    | P7_    | P6_    | P5_    | P4_    | P3_    | P2_    | P1_    |
| R/W    | PREMIX |

Reset Value 0x00

1b0: premixing off

1b1: premixing on

The time of each Px\_PREHEAT and Px\_PREMIX period can be calculated as

Px\_PRETIME (in 
$$\mu$$
s) = 
$$\frac{(Px_PRETIME - 5) \cdot HMAX}{120}$$

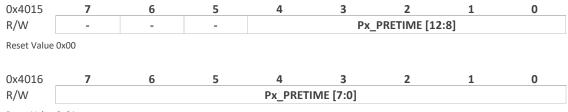
(eq.4, in output mode A&B)

• Px\_PRETIME (in 
$$\mu$$
s) =  $\frac{(Px_PRETIME - 9) \cdot HMAX}{120}$ 

(eq.5, in other output modes)

Note: Px PRETIME + Px INTEGRATION should not exceed 1ms.

Px\_PRETIME register value can be calculated out of equation 4 or 5. (value 0 is not allowed)



Reset Value 0x0A

Note: Px\_PREHEAT & Px\_PREMIX will increase the system power consumption

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When enabling premixing these other register values have to be updated

| 0x5281      | 7                | 6 | 5 | 4      | 3          | 2         | 1 | 0 |  |
|-------------|------------------|---|---|--------|------------|-----------|---|---|--|
| R/W         | -                | - |   |        | RANDNM     | 7 [21:16] |   |   |  |
| Reset Value | Reset Value 0x00 |   |   |        |            |           |   |   |  |
|             |                  |   |   |        |            |           |   |   |  |
| 0x5282      | 7                | 6 | 5 | 4      | 3          | 2         | 1 | 0 |  |
| R/W         |                  |   |   | RANDNI | //7 [15:8] |           |   |   |  |
| Reset Value | 0x05             |   |   |        |            |           |   |   |  |
|             |                  |   |   |        |            |           |   |   |  |
| 0x5283      | 7                | 6 | 5 | 4      | 3          | 2         | 1 | 0 |  |
| R/W         |                  |   |   | RANDN  | M7 [7:0]   |           |   |   |  |
|             |                  |   |   |        |            |           |   |   |  |

Reset Value 0x55

 $\text{RANDNM7 can be calculated as } 1070 + \text{HMAX} \cdot \text{ROUNDUP}\left(\frac{\text{Px\_PRETIME (in } \mu s) - 1 \ , 13}{\text{HMAX}} \cdot 120; 0\right)$ 



# 7.13. Px\_INTEGRATION

The integration time is configurable for each phase individually. When updating the registers it's advised to use PARAM\_HOLD like explained in section 0.

The next boundary conditions have to be taken into account :

- $\frac{\text{HMAX}}{120} \, \mu\text{s} < \text{integration time} < 1\text{ms}$
- in steps of  $\frac{\text{HMAX}}{120} \mu \text{s}$
- $\frac{\text{Total IntegrationTime}}{\text{Total Frame Time}} = \frac{\sum_{x=0}^{7} P_{x}\text{INTEGRATION} + P_{x}\text{PRETIME}}{\text{Total FRAME\_TIME}} < 0.4$

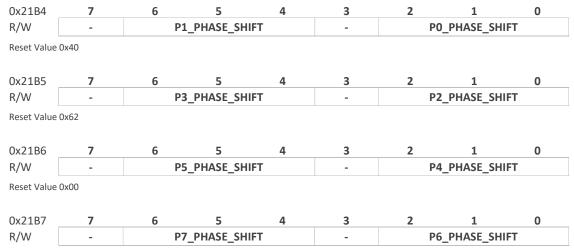
The value of registers Px\_INTEGRATION can be calculated as FLOOR  $\left(\frac{\text{Integration Time (in } \mu s) \cdot 120}{\text{HMAX}}\right)$  · HMAX

| Register<br>Address |     | Register Name          | Default<br>Value |
|---------------------|-----|------------------------|------------------|
| 0x2120              | R/W | PO INTEGRATION [31:24] | 0x00             |
| 0x2121              | R/W | PO INTEGRATION [23:16] | 0x01             |
| 0x2122              | R/W | PO_INTEGRATION [15:8]  | 0xD4             |
| 0x2123              | R/W | PO_INTEGRATION [7:0]   | 0xC0             |
| 0x2124              | R/W | P1 INTEGRATION [31:24] | 0x00             |
| 0x2125              | R/W | P1 INTEGRATION [23:16] | 0x01             |
| 0x2126              | R/W | P1 INTEGRATION [15:8]  | 0xD4             |
| 0x2127              | R/W | P1 INTEGRATION [7:0]   | 0xC0             |
| 0x2128              | R/W | P2 INTEGRATION [31:24] | 0x00             |
| 0x2129              | R/W | P2 INTEGRATION [23:16] | 0x01             |
| 0x212A              | R/W | P2 INTEGRATION [15:8]  | 0xD4             |
| 0x212B              | R/W | P2 INTEGRATION [7:0]   | 0xC0             |
| 0x212C              | R/W | P3 INTEGRATION [31:24] | 0x00             |
| 0x212D              | R/W | P3 INTEGRATION [23:16] | 0x01             |
| 0x212E              | R/W | P3 INTEGRATION [15:8]  | 0xD4             |
| 0x212F              | R/W | P3_INTEGRATION [7:0]   | 0xC0             |
| 0x2130              | R/W | P4 INTEGRATION [31:24] | 0x00             |
| 0x2131              | R/W | P4 INTEGRATION [23:16] | 0x01             |
| 0x2132              | R/W | P4 INTEGRATION [15:8]  | 0xD4             |
| 0x2133              | R/W | P4 INTEGRATION [7:0]   | 0xC0             |
| 0x2134              | R/W | P5 INTEGRATION [31:24] | 0x00             |
| 0x2135              | R/W | P5 INTEGRATION [23:16] | 0x01             |
| 0x2136              | R/W | P5_INTEGRATION [15:8]  | 0xD4             |
| 0x2137              | R/W | P5_INTEGRATION [7:0]   | 0xC0             |
| 0x2138              | R/W | P6 INTEGRATION [31:24] | 0x00             |
| 0x2139              | R/W | P6 INTEGRATION [23:16] | 0x01             |
| 0x213A              | R/W | P6 INTEGRATION [15:8]  | 0xD4             |
| 0x213B              | R/W | P6 INTEGRATION [7:0]   | 0xC0             |
| 0x213C              | R/W | P7 INTEGRATION [31:24] | 0x00             |
| 0x213D              | R/W | P7 INTEGRATION [23:16] | 0x01             |
| 0x213E              | R/W | P7 INTEGRATION [15:8]  | 0xD4             |
| 0x213F              | R/W | P7_INTEGRATION [7:0]   | 0xC0             |

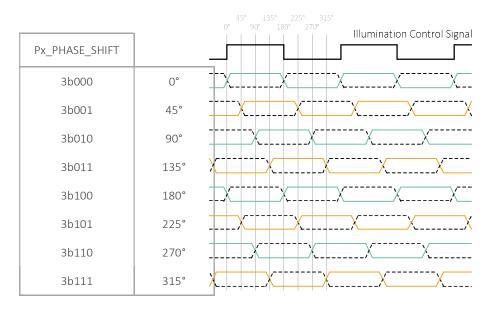


# 7.14. Px\_PHASE\_SHIFT

The phase shift difference between the internal modulation signal (towards the pixels) and the external illumination control signal can be set for each phase independently in steps of 45deg. This phase shift can be calculated as  $360 * Px_PHASE_SHIFT / 8$ .



Reset Value 0x00



The illumination signal towards the pixels is used as reference by default and the modulation signal towards the pixels (LEDP/LEDN) is shifted in phase. This reference signal can be selected<sup>1</sup>.

| 0x4EA0 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0      |
|--------|---|---|---|---|---|---|---|--------|
| R/W    | - | - | - | - | - | - | - | MODREF |

Reset Value 0x00

- 1b0: illumination signal is used as reference, internal modulation signal is shifted in phase
- 1b1: internal modulation signal is used as reference, illumination signal is shifted in phase

<u>Note</u><sup>1</sup>: Changing the reference signal will impact the raw to distance calculation, additionally, This feature is not available on AAA-200 product variants (see section Ordering Information)



## 7.15. Px\_PHASE\_IDLE (or V-blanking)

An artificial idle time (wait time or V-blanking) between 2 subsequent phases can be configured. This function negatively impacts the system motion robustness (= the ability to measure fast moving objects), but it can be used for compatibility with certain microcontrollers.

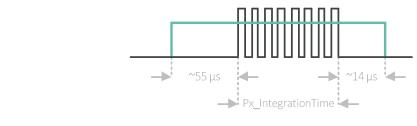
Phase idle time (in ms) can be calculated as  $\frac{Px\_PHASE\_IDLE \cdot HMAX}{120 \cdot 10^3}$ 

| Register<br>Address |     | Register Name  | Default<br>Value |
|---------------------|-----|----------------|------------------|
| 0x21C8              | R/W | P0_PHASE_IDLE* | 0x05             |
| 0x21C9              | R/W | P1_PHASE_IDLE* | 0x05             |
| 0x21CA              | R/W | P2_PHASE_IDLE* | 0x05             |
| 0x21CB              | R/W | P3_PHASE_IDLE* | 0x05             |
| 0x21CC              | R/W | P4_PHASE_IDLE* | 0x05             |
| 0x21CD              | R/W | P5_PHASE_IDLE* | 0x05             |
| 0x21CE              | R/W | P6_PHASE_IDLE* | 0x05             |
| 0x21CF              | R/W | P7_PHASE_IDLE* | 0x05             |

<sup>\*</sup> Values outside [0x05 - 0xFF] are prohibited

# 7.16. Px\_LEDEN

Enable or disable the LEDEN pulse(s). This pulse starts  $\sim$ 55µs before the integration time and ends  $\sim$ 14µs after the integration time. It can be used as an extra control signal for the illumination (for example enable/disable the PSU) or to disable any significant external noise influencers during the integration time & pixel readout time. It can be enabled/disabled for each of the phases individually. The electrical pulse toggles between GND and VIF.





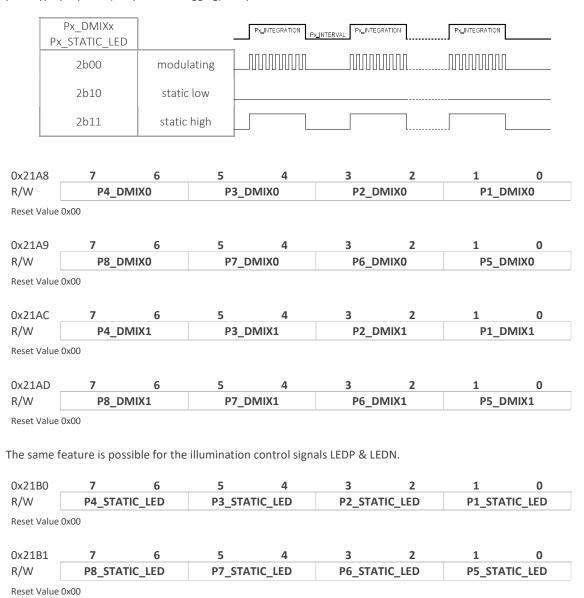
Reset Value 0x00

- 1b0: LEDEN pulse disabled
- 1b1: LEDEN pulse enabled



# 7.17. Px\_DMIX0, Px\_DMIX1 & Px\_STATIC\_LED

The patented Depthsense® pixel design includes 2 internal digital control signals, DMIX0 & DMIX1, that actively forces a guiding field inside the pixel and thus drives, by light photons generated, electrons either to pixel tap A or pixel tap B. In normal operating conditions these signals are modulating during Px\_INTEGRATION, but for prototype purposes (or system debugging) it is possible to define their internal behaviour.





## 7.18. Pixel Binning

Pixel binning is a technique to combine individual pixels together to create a set of *superpixels*. In binning mode, each pixel is read-out separately but is recombined digitally with its neighbouring pixels inside the sensor to increase the SNR (signal-to-noise ratio) and to decrease the data processing & bandwidth towards the microcontroller. There's no beneficial effect on the total read-out time (= no impact on motion robustness) as each pixel still has to be read out individually. The noise from the pixels is dominated by the photon shot noise according to a Poisson distribution, with a SNR in binning mode proven to increase with  $\sqrt{<$  number of binned pixels >.

| 0x14A5 | 7 | 6 | 5 | 4 | 3 | 2 | 1       | 0      |
|--------|---|---|---|---|---|---|---------|--------|
| R/W    | - | - | - | - | - | - | BINNING | G_MODE |

Reset Value 0x00

- 2b00: no binning (= VGA resolution, 640x480 pixels)
- 2b01: 2x2 binning (= QVGA resolution, 320x240 pixels)
- 2b10: 4x4 binning (= QQVGA resolution, 160x120 pixels)
- 2b11: 8x8 binning (= QQQVGA resolution, 80x60 pixels)



# 7.19. Region of Interest (ROI)

Not all applications require the full VGA (640x480) pixel information. To reduce the total frame readout time, the data processing (or bandwidth) and power consumption it is possible to select only a subset of pixels eligible for readout, also known as a region of interest (ROI). Rows have to be read-out in multiples of 2.

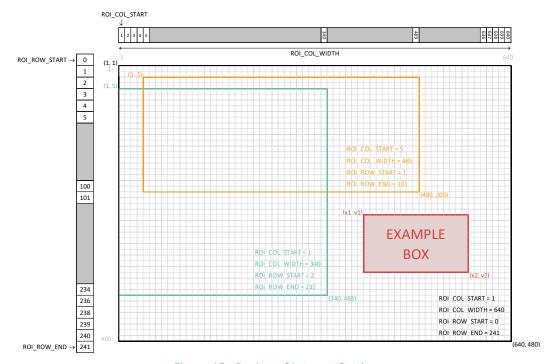


Figure 18 : Region of Interest Settings

<u>Note</u>: Changing registers IMG\_ORIENTATION\_H or IMG\_ORIENTATION\_V (from section 7.20) also requires the user to reverse the applicable ROI registers for the same region to be readout.

| Register<br>Address <sup>1</sup> | Register Name        | Calculated<br>Register Value |
|----------------------------------|----------------------|------------------------------|
| 0x0804 [5:0]                     | ROI_COL_START [13:8] | x1                           |
| 0x0805                           | ROI_COL_START [7:0]  | XI                           |
| 0x0806 [1:0]                     | ROI_COL_WIDTH [9:8]  | x2 - x1 + 1                  |
| 0x0807                           | ROI_COL_WIDTH [7:0]  | X2 - X1 + 1                  |
| 0x0808 [0]                       | ROI_ROW_START [8]    | (1 1) / 2                    |
| 0x0809                           | ROI_ROW_START [7:0]  | (y1 – 1) / 2                 |
| 0x080A [0]                       | ROI_ROW_END [8]      | v2 / 2 + 1                   |
| 0x080B                           | ROI_ROW_END [7:0]    | y2 / 2 + 1                   |

When defining the ROI region there is a list of minimum requirements that have to be taken into account:

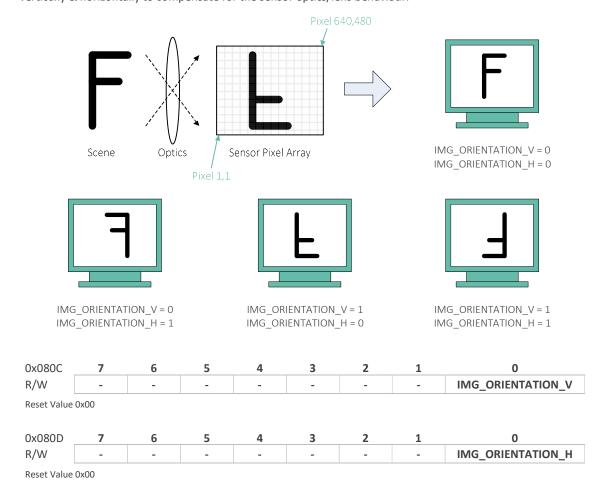
| Binning | Minimum ROI | Min. Column Increment x1,x2 | Min. Row Increment y1,y2 |
|---------|-------------|-----------------------------|--------------------------|
| x1      | 8 x 2       | multiple of 4               | multiple of 2            |
| x2      | 16 x 2      | multiple of 8               | multiple of 2            |
| x4      | 32 x 4      | multiple of 16              | multiple of 4            |
| х8      | 64 x 8      | multiple of 32              | multiple of 8            |



## 7.20. Flip & Mirror

The physical sensor orientation on a PCB does not always match with application requirements or with a visually attractive picture for the user. For that reason the images can be vertically flipped and/or horizontally mirrored before they are outputted via the video output interface.

The default read out position starting at pixel 1, like visualized in section 4.1, already inverts the image both vertically & horizontally to compensate for the sensor optics/lens behaviour.



# 7.21. Temperature Sensor

The internal junction temperature sensor information is available as a register value (or can be found inside the MetaData). The temperature is read right after the integration time and just before the frame readout period like shown in 7.8. It is only valid after the first phase acquisition. It has an absolute accuracy of  $\pm 5$  °C.



Temperature [in °C] = TEMP VALUE - 40



### 7.22. Pixel & Phase Statistics

MLX75027 monitors each raw tap A and tap B value separately. Statistics are gathered when either of the two taps exceeds their minimum or maximum threshold. Feedback is provided as a single bit error flag or generic pixel error code via the metadata (or via I<sup>2</sup>C). This data can be used as indicator to warn for pixel saturation or extreme low light conditions. The total amount of erroneous pixels violating their thresholds can be found in Px\_ERRORCOUNTLOW or Px\_ERRORCOUNTHIGH registers for each phase.

| 0x1433 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0        |
|--------|---|---|---|---|---|---|---|----------|
| R/W    | - | - | - | - | - | - | - | STATS_EN |

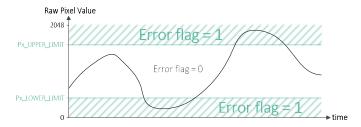
Reset Value 0x00

1b0: statistics disabled1b1: statistics enabled

| 0x14BB | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0          |
|--------|---|---|---|---|---|---|---|------------|
| R/W    | - | - | - | - | - | - | - | STATS_MODE |

Reset Value 0x00

1b0: pixel error flag enabled



1b1: pixel error code enabled

The pixel error code is only available for output mode A-B and A+B as shown in Table 13. Please note the pixel error flag replaces the pixel MSB.

| Data<br>Output<br>Mode | STATS_EN = 0                    | STATS_EN = 1                                      |   |  |  |
|------------------------|---------------------------------|---|---|--|--|
|                        |                                 | STATS_MODE = 0<br>(Error flag enabled)            | STATS_MODE = 1<br>(Error code enabled)                    |  |  |
| A-B                    | [11:0] = pixel data (signed)    | [11] = error flag<br>[10:0] = pixel data (signed) | [11:0] = pixel data (signed)<br>or 0x800 (= error code)   |  |  |
| A+B                    | [11:0] = pixel data (unsigned)  | [11] = error flag<br>[10:0] = pixel data          | [11:0] = pixel data (unsigned)<br>or 0xFFF (= error code) |  |  |
| A<br>B<br>A&B          | [11] = 0<br>[10:0] = pixel data | [11] = error flag<br>[10:0] = pixel data          | [11] = 0<br>[10:0] = pixel data                           |  |  |

Table 13: Register Table for Error Info

#### MLX75027 VGA Time-of-Flight Sensor





The minimum threshold for each tap is defined in  $Px\_LOWER\_LIMIT$ .

| Register Address |     | Register Name         | Default Value |
|------------------|-----|-----------------------|---------------|
| 0x1434           | R/W | P1_LOWER_LIMIT [10:8] | 0x00          |
| 0x1435           | R/W | P1_LOWER_LIMIT [7:0]  | 0x00          |
| 0x1436           | R/W | P2_LOWER_LIMIT [10:8] | 0x00          |
| 0x1437           | R/W | P2_LOWER_LIMIT [7:0]  | 0x00          |
| 0x1438           | R/W | P3_LOWER_LIMIT [10:8] | 0x00          |
| 0x1439           | R/W | P3_LOWER_LIMIT [7:0]  | 0x00          |
| 0x143A           | R/W | P4_LOWER_LIMIT [10:8] | 0x00          |
| 0x143B           | R/W | P4_LOWER_LIMIT [7:0]  | 0x00          |
| 0x143C           | R/W | P5_LOWER_LIMIT [10:8] | 0x00          |
| 0x143D           | R/W | P5_LOWER_LIMIT [7:0]  | 0x00          |
| 0x143E           | R/W | P6_LOWER_LIMIT [10:8] | 0x00          |
| 0x143F           | R/W | P6_LOWER_LIMIT [7:0]  | 0x00          |
| 0x1440           | R/W | P7_LOWER_LIMIT [10:8] | 0x00          |
| 0x1441           | R/W | P7_LOWER_LIMIT [7:0]  | 0x00          |
| 0x1442           | R/W | P8_LOWER_LIMIT [10:8] | 0x00          |
| 0x1443           | R/W | P8_LOWER_LIMIT [7:0]  | 0x00          |

The maximum threshold for each tap is defined in Px\_UPPER\_LIMIT.

| Register Address |     | Register Name         | Default Value |
|------------------|-----|-----------------------|---------------|
| 0x1448           | R/W | P1_UPPER_LIMIT [10:8] | 0x00          |
| 0x1449           | R/W | P1_UPPER_LIMIT [7:0]  | 0x00          |
| 0x144A           | R/W | P2_UPPER_LIMIT [10:8] | 0x00          |
| 0x144B           | R/W | P2_UPPER_LIMIT [7:0]  | 0x00          |
| 0x144C           | R/W | P3_UPPER_LIMIT [10:8] | 0x00          |
| 0x144D           | R/W | P3_UPPER_LIMIT [7:0]  | 0x00          |
| 0x144E           | R/W | P4_UPPER_LIMIT [10:8] | 0x00          |
| 0x144F           | R/W | P4_UPPER_LIMIT [7:0]  | 0x00          |
| 0x1450           | R/W | P5_UPPER_LIMIT [10:8] | 0x00          |
| 0x1451           | R/W | P5_UPPER_LIMIT [7:0]  | 0x00          |
| 0x1452           | R/W | P6_UPPER_LIMIT [10:8] | 0x00          |
| 0x1453           | R/W | P6_UPPER_LIMIT [7:0]  | 0x00          |
| 0x1454           | R/W | P7_UPPER_LIMIT [10:8] | 0x00          |
| 0x1455           | R/W | P7_UPPER_LIMIT [7:0]  | 0x00          |
| 0x1456           | R/W | P8_UPPER_LIMIT [10:8] | 0x00          |
| 0x1457           | R/W | P8_UPPER_LIMIT [7:0]  | 0x00          |

#### MLX75027 VGA Time-of-Flight Sensor





The total amount of pixels that violate their limit can be read in separate registers:

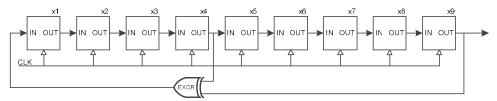
| Register Address |     | Register Name          | Default Value |
|------------------|-----|------------------------|---------------|
| 0x145D [3:0]     | R/W | PO_ERRCOUNTLOW [19:16] | 0x00          |
| 0x145E           | R/W | PO_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x145F           | R/W | PO_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1461 [3:0]     | R/W | P1_ERRCOUNTLOW [19:16] | 0x00          |
| 0x1462           | R/W | P1_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x1463           | R/W | P1_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1465 [3:0]     | R/W | P2_ERRCOUNTLOW [19:16] | 0x00          |
| 0x1466           | R/W | P2_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x1467           | R/W | P2_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1469 [3:0]     | R/W | P3_ERRCOUNTLOW [19:16] | 0x00          |
| 0x146A           | R/W | P3_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x146B           | R/W | P3_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x146D [3:0]     | R/W | P4_ERRCOUNTLOW [19:16] | 0x00          |
| 0x146E           | R/W | P4_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x146F           | R/W | P4_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1471 [3:0]     | R/W | P5_ERRCOUNTLOW [19:16] | 0x00          |
| 0x1472           | R/W | P5_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x1473           | R/W | P5_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1475 [3:0]     | R/W | P6_ERRCOUNTLOW [19:16] | 0x00          |
| 0x1476           | R/W | P6_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x1477           | R/W | P6_ERRCOUNTLOW [7:0]   | 0x00          |
| 0x1479 [3:0]     | R/W | P7_ERRCOUNTLOW [19:16] | 0x00          |
| 0x147A           | R/W | P7_ERRCOUNTLOW [15:8]  | 0x00          |
| 0x147B           | R/W | P7_ERRCOUNTLOW [7:0]   | 0x00          |

| Register Address |     | Register Name           | Default Value |
|------------------|-----|-------------------------|---------------|
| 0x1481 [3:0]     | R/W | PO_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x1482           | R/W | PO_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x1483           | R/W | PO_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x1485 [3:0]     | R/W | P1_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x1486           | R/W | P1_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x1487           | R/W | P1_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x1489 [3:0]     | R/W | P2_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x148A           | R/W | P2_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x148B           | R/W | P2_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x148D [3:0]     | R/W | P3_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x148E           | R/W | P3_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x148F           | R/W | P3_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x1491 [3:0]     | R/W | P4_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x1492           | R/W | P4_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x1493           | R/W | P4_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x1495 [3:0]     | R/W | P5_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x1496           | R/W | P5_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x1497           | R/W | P5_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x1499 [3:0]     | R/W | P6_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x149A           | R/W | P6_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x149B           | R/W | P6_ERRCOUNTHIGH [7:0]   | 0x00          |
| 0x149D [3:0]     | R/W | P7_ERRCOUNTHIGH [19:16] | 0x00          |
| 0x149E           | R/W | P7_ERRCOUNTHIGH [15:8]  | 0x00          |
| 0x149F           | R/W | P7_ERRCOUNTHIGH [7:0]   | 0x00          |



#### 7.23. PN9 Test Pattern

MLX75027 has a built-in test pattern to verify the MIPI connectivity. This can be used for debugging purposes, but also as live diagnostic. The pattern is a pseudorandom code generated using a nine stage shift register.



At  $t_0$  each shift register is pre-loaded with one. At every clock pulse the register shifts and the first stage input is replaced with the exclusive disjunction (EXOR operation) from bit 4 and 9. The output stream of register no.9 is recombined into an 8bit word. This sequence generates 512 unique values and will repeat itself.

|                            | MSB LSB   |         |   |  |  |  |  |
|----------------------------|-----------|---------|---|--|--|--|--|
|                            | x9 ➤ 1    | 1 1 1 1 | 1 1 1 1 t <sub>0</sub>                    |  |  |  |  |
|                            | x9 ➤ 0 1  | 1 1 1 1 | 1 1 1 1 t <sub>1</sub>                    |  |  |  |  |
| >                          | 9 > 0 0 1 | 1 1 1 1 | 1 1 1 1 t <sub>2</sub>                    |  |  |  |  |
| x9 ▶                       | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 <b>&gt;</b> 0           | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 1 0                   | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 1 1 0                 | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ▶ 1 1 1 0               | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 1 1 1 1 0             | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 0 1 1 1 1 0           | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 1 0 1 1 1 0           | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 > 1 1 0 1 1 1 1 0       | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 ➤ 1 1 1 0 1 1 1 0       | 0 0 0 1   | 1 1 1 1 | 1 1 1 1                                   |  |  |  |  |
| x9 > 0 1 1 1 0 1 1 1 0     | 0 0 0 1   | 1 1 1 1 | 1 1 1 1 t <sub>x-2</sub>                  |  |  |  |  |
| x9 > 0 0 1 1 1 0 1 1 1 0   | 0 0 0 1   | 1 1 1 1 | 1 1 1 1 t <sub>x-1</sub>                  |  |  |  |  |
| x9 > 0 0 0 1 1 1 0 1 1 1 0 | 0 0 0 1   | 1 1 1 1 | $1 \  \   1 \  \   1 \  \   1 \  \   t_x$ |  |  |  |  |
|                            |           |         |   |  |  |  |  |
| 1 D E                      | 1         | F       | F   |  |  |  |  |
|                            |           |         |   |  |  |  |  |

Recombining this example bitstream into a single MIPI package, like explained in section 5.2.2, becomes 0xFFE11D, which translates into the first two pixels values 0xFFD (4093) and 0xE11 (3601). The bitstream of the next 2 pixels gives 0x85ED9A, which corresponds to a MIPI package of 0x9AED85, representing two pixel values 0x9A5 (2469) and 0xED8 (3800), ....

The test pattern is independent of the pixel values and output mode but is visually different for mode A&B.

To enable the test pattern, please follow this register sequence:

- Register 0x1405 > value 0x00
- Register 0x1406 > value 0x04
- Register 0x1407 > value 0x01

To disable the test pattern:

Register 0x1407 > value 0x00

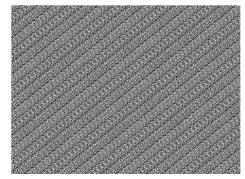


Figure 19: Visual representation of PN9 Test Pattern



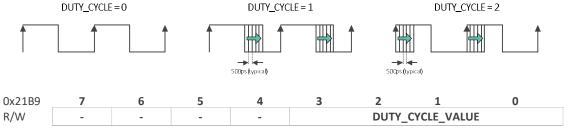
# 7.24. Duty Cycle Adjustment

It is possible to adjust the duty cycle of the illumination signals (LEDP, LEDN). The default duty cycle is 50%, but it can be optimized to compensate certain driver effects. The adjustment is controlled by analogue circuitry in 16 delay steps (on the rising or falling edge of the light pulses). Each step is typically 500ps, but the absolute delay time is affected by process & temperature variation.

| 0x4E9E | 7 | 6 | 5 | 4 | 3 | 2 | 1       | 0   |
|--------|---|---|---|---|---|---|---------|-----|
| R/W    | - | - | - | - | - |   | DUTY_CY | CLE |

Reset Value 0x00

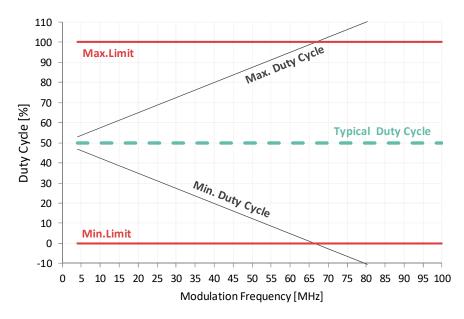
- 2b00: no duty cycle correction (= disabled)
- 2b01: time delay on the falling edge (= increased duty cycle)
- 2b10: time delay on the rising edge (= decreased duty cycle) (other values are prohibited)



Reset Value 0x00

The total delay (of the rising and falling edge) = DUTY\_CYCLE\_VALUE · 500 ps (typical value)

Since the step size has an absolute value the duty cycle limits are affected by the modulation frequency. It's the user responsibility to stay within min. & max. limits to avoid illumination hardware failure.



This graph for example shows that the duty cycle at 40 MHz can be changed between 20 & 80 %.



# 7.25. Illumination Signal (subLVDS or CMOS)

The illumination signal is available as differential signal (subLVDS) or as single ended pulses (CMOS). It is suggested to apply changes to this hardware configuration during the *Software Standby* mode.

| 0x10E2 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0       |
|--------|---|---|---|---|---|---|---|---------|
| R/W    | - | - | - | - | - | - | - | LVDS_EN |

Reset Value 0x01

- 1b0: CMOS mode (LEDP = LEDN)
- 1b1: subLVDS mode (LEDP positive, LEDN negative)

# 8. MetaData Description

MetaData or embedded data is available on two lines after the normal pixel data. These lines can be enabled via EN\_META in register 0x3C18. Each line features 132 unique values.

| 0x3C18 | 7 | 6 | 5 | 4 | 3 | 2 | 1    | 0    |
|--------|---|---|---|---|---|---|------|------|
| R/W    | - | - | - | - | - | - | EN_N | ЛЕТА |

Reset Value 0x02

- 2b00: no metadata lines enabled
- 2b01: first metadata line (line #1) enabled
- 2b10: first & second metadata lines (line #1 and line #2) enabled (other values are prohibited)

| Line | Pixel | Description   |
|------|-------|---|
| #1   | E000  | 0x0A (= fixed value)  |
| #1   | E042  | IMG_ORIENTATION_V   |
| #1   | E044  | IMG_ORIENTATION_H   |
| #1   | E058  | USER_ID   |
| #1   | E062  | OUTPUT_MODE   |
| #1   | E068  | DATA_LANE_CONFIG  |
| #1   | E078  | [11:4] TEMP_VALUE<br>[3] 1b0 (= fixed value)<br>[2] 1b1 (= fixed value)<br>[1] 1b0 (= fixed value)<br>[0] 1b1 (= fixed value) |
| #1   | E082  | BINNING_MODE  |
| #1   | E096  | DIVSEL  |
| #1   | E098  | DIVSELPRE   |
| #1   | E127  | End of Data 0x07  |
| #1   | E128  | End of Data 0x07  |
| #1   | E129  | End of Data 0x07  |
| #1   | E130  | End of Data 0x07  |
| #1   | E131  | End of Data 0x07  |

| Line | Pixel | Description                                       |
|------|-------|---|
| #2   | E050  | ERRCOUNTLOW [19:16]                               |
| #2   | E052  | ERRCOUNTLOW [15:8]                                |
| #2   | E054  | ERRCOUNTLOW [7:0]                                 |
| #2   | E058  | ERRCOUNTHIGH [19:16]                              |
| #2   | E060  | ERRCOUNTHIGH [15:8]                               |
| #2   | E062  | ERRCOUNTHIGH [7:0]                                |
| #2   | E090  | FRAME_COUNT<br>(= framecounter)                   |
| #2   | E096  | PHASE_COUNT<br>(= number of phase inside a frame) |
| #2   | E127  | End of Data 0x07                                  |
| #2   | E128  | End of Data 0x07                                  |
| #2   | E129  | End of Data 0x07                                  |
| #2   | E130  | End of Data 0x07                                  |
| #2   | E131  | End of Data 0x07                                  |



RAW12 output example (assuming single data lane configuration):



The data in each line is composed of a tag, data & dummy byte.

Each uneven pixel (E001, E003, E005, ... ) is an embedded data line tag.



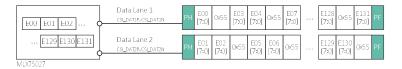
#### Tag values are listed below:

| Tag  | Data Byte Description  |
|------|--|
| 0x00 | Illegal tag, if found treat as End of Data   |
| 0x07 | End of Data  |
| 0xAA | CCI register Index MSB [15:8]  |
| 0xA5 | CCI register Index LSB [7:0]   |
| 0x5A | Auto increment the CCI index after the data byte – valid data                          |
|      | (Data byte contains valid CC register data)  |
| 0x55 | Auto increment the CCI index after the data byte – null data.                          |
|      | (A CCI register does NOT exist for the current CCI index, the data byte value is 0x07) |
| 0xFF | Illegal tag, if found treat as End of Data   |

# 8.1. Embedded Data Format in 4 Lane MIPI Configuration



# 8.2. Embedded Data Format in 2 Lane MIPI Configuration





# 9. Distance & Amplitude Calculation

The distance data per pixel [in mm] can be calculated with the following formulas:

```
p0 = TwoComp_MKO(phase0);
p180 = TwoComp_MKO(phase180);
p90 = TwoComp_MKO(phase90);
p270 = TwoComp_MKO(phase270);

I = p0 - p180;
Q = p270 - p90;

ampData = sqrt(I.^2 + Q.^2);
Phase = atan2(I, Q);
unAmbiguousRange = 0.5*299792458/ModF*1000;
coef_rad = unAmbiguousRange / (2*pi);
distData = (Phase+pi) * coef_rad;
while sum(distData(distData<0)) ~= 0
    distData(distData<0) = distData(distData<0) + unAmbiguousRange;
end</pre>
```

Figure 20: Example Matlab code of the raw to distance data calculation

- phase0, phase180, phase90, phase270 are the raw A-B frames from the sensor at each phase interval
- TwoComp\_MKO is a local function that converts the unsigned data from Mode A-B for each of the raw phases into signed values
- unAmbigiousRange is the maximum range determined by the system modulation frequency (at modulation frequency of 20MHz this would be ~7.49m, at 100MHz it will be ~1.49m)
- coef\_rad is a conversion coefficient from radians to degree
- The while loop avoids negative distance values by adding the unAmbiguousRange to these negative distance pixels



# **10.** Package Outline

# 10.1. Pinout & Equivalent I/O Circuitry

| Designator | Pin | Function   | Voltage<br>Domain | Equivalent I/O Circuitry                    |
|------------|-----|--|-------------------|---|
| SLASEL     | A4  | Slave select, choose between I <sup>2</sup> C slave address 0x57 or 0x67 (digital input) | 0 - 1V8           | VDD***  ✓ Input  ✓ GND                      |
| TRIGGER    | K11 | Trigger input with MODE=0, trigger output indicator with MODE=1 (active low digital I/O) | 0 - 1V8           | VDD***    100 kΩ   VDD***   2 in/out   *GND |
| SCL        | B5  | I <sup>2</sup> C clock (digital I/O)   | 0 - 1V8           | VDD***                                      |
| SDA        | A5  | I <sup>2</sup> C data (digital I/O)  | 0 - 1V8           | *GND  |
| LEDEN      | К3  | Optional external control signal (digital output)  | 0 - 1V8           | VDD***  VDD***  in/out  *GND                |
| LEDP       | L3  | Positive differential illumination control signal  | 0 - 1V8           | VDD***  → × × LEDP                          |
| LEDN       | L4  | Negative differential illumination control signal  | 0 - 1V8           | *GND  |
| CLK        | В3  | Input clock of 8 MHz<br>(digital input)  | 0 - 1V8           | —◆ VDD***                                   |
| LEDFB      | L2  | LED feedback control (digital input)   | 0 - 1V8           | ▼ input input                               |
| RESETB     | A2  | Generic device reset (active low digital input)  | 0 - 1V8           | *GND  |
| CSI_CLKN   | G1  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_CLKP   | G2  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT1N  | H2  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT1P  | H1  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT2N  | F1  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT2P  | F2  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT3N  | J2  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT3P  | J1  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT4N  | E1  | Digital output   |                   | MIPI D-PHY                                  |
| CSI_DAT4P  | E2  | Digital output   |                   | MIPI D-PHY                                  |

Table 14a: Pinout



| Designator | Pin   | Function                                       | Voltage<br>Domain | I/O Equivalent Circuitry |
|------------|---|--|-------------------|--------------------------|
| VDDA       | A7<br>B2<br>C12<br>E12<br>G12<br>M2<br>M11                  | Analog supply voltage                          | 2V7               |                          |
| VDDD       | C2<br>C3<br>D1<br>K1<br>K2                                  | Digital supply voltage                         | 1V2               | VDD***                   |
| VDDMIX     | L5<br>L6<br>L7<br>L8<br>L9<br>L10                           | High current supply voltage for the mix driver | 1V2               |                          |
| VDDIF      | A3<br>B6<br>L1<br>B12                                       | Supply voltage for I/O interface               | 1V8               |                          |
| VBO1       | E11   | Decoupled to AGND (4.7μF)                      | 2V7               | n/A                      |
| VBO2       | G11   | Decoupled to AGND (4.7 $\mu$ F)                | 2V7               | n/A                      |
| VRSTL      | F12   | Decoupled to AGND (1 $\mu$ F)                  | -1V0              | n/A                      |
| VRL1       | C11   | Decoupled to AGND (4.7 $\mu$ F)                | -1V2              | n/A                      |
| VRL2       | F11   | Decoupled to AGND (4.7μF)                      | -1V2              | n/A                      |
| AGND       | B1<br>B8<br>B11<br>D11<br>D12<br>M5<br>M6<br>M7<br>M8<br>M9 | Analog ground                                  | GND               | VDD***                   |
| DGND       | A8 A9 A10 A11 B9 B10 C1 C4 C5 C6                            | Digital ground                                 | GND               | <b>⊠</b> *GND            |

Table 4b : Pinout



| Designator          | Pin   | Function       | Voltage<br>Domain | I/O Equivalent Circuitry |
|---------------------|---|----------------|-------------------|--------------------------|
| DGND<br>(continued) | C8 C9 C10 D2 D3 D4 D5 D6 D7 D8 D9 D10 E3 E4 E5 E6 E7 E8 E9 E10 G3 G4 G5 G6 G7 G8 G9 G10 H3 H4 H5 H6 H7 H8 H9 H10 J3 J4 J5 J6 J7 J8 J9 J10 | Digital ground | GND               | VDD***  ▼GND             |

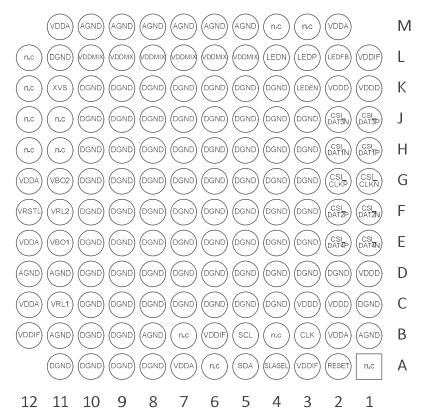
Table 4c : Pinout



| Designator          | Pin  | Function       | Voltage<br>Domain | I/O Equivalent Circuitry |
|---------------------|--|----------------|-------------------|--------------------------|
| DGND<br>(continued) | K4<br>K5<br>K6<br>K7<br>K8<br>K9<br>K10                                    | Digital ground | GND               | VDD***  ▼GND             |
| n.c.                | A1<br>A6<br>B4<br>B7<br>H11<br>H12<br>J11<br>J12<br>K12<br>L12<br>M3<br>M4 | Do not connect | Floating          | n/A                      |

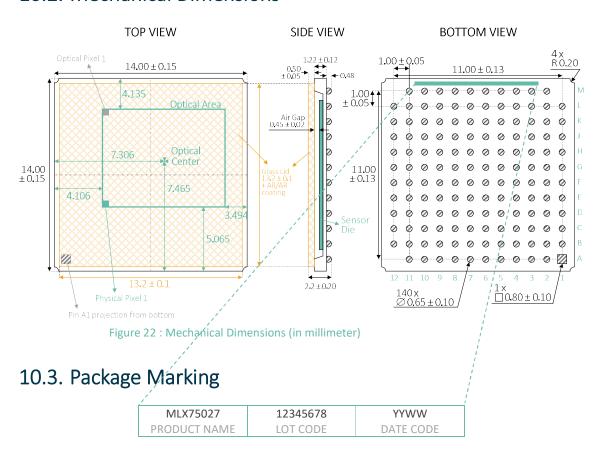
Table 4d : Pinout

# An overlay of these pins and the package can be found here: $\begin{tabular}{ll} \bf BOTTOM\ VIEW \end{tabular}$



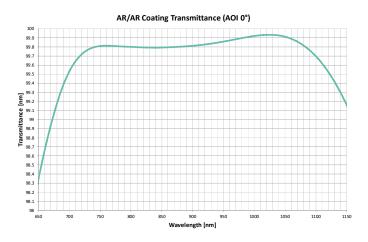


## 10.2. Mechanical Dimensions



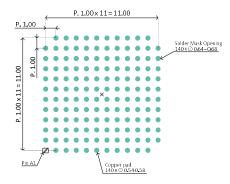
# 10.4. AR/AR Coating

The double sided anti-reflective coating covers the complete glass lid as seen in the Mechanical Dimensions.





# 10.5. PCB Landing Pattern



#### 10.6. Reflow Solder Profile

MLX75027 reflow temperature profile is based on IPC/JEDEC joint industry standard J-STD-020C Rev C.

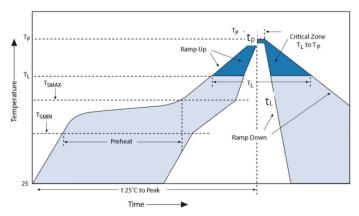


Figure 23: J-STD-020C reflow temperature profile

| Profile Feature                            | Symbol                                | Lead-Free Assembly |
|--|---------------------------------------|--------------------|
| Average ramp up rate                       | Ramp Up                               | 3°C / second max.  |
| Preheat temperature                        | T <sub>SMIN</sub> — T <sub>SMAX</sub> | 150°C - 200°C      |
| Preheat time                               | Preheat                               | 60 - 180 seconds   |
| Peak temperature                           | T <sub>L</sub> - T <sub>P</sub>       | 245°C - 60°C       |
| Time within 5°C of actual peak temperature | t <sub>P</sub> - t <sub>L</sub>       | 20 - 40 seconds    |
| Ramp down rate                             | Ramp Down                             | 6°C / second max.  |
| Time 25°C to peak temperature              | T 25°C to Peak                        | 8 minutes max.     |

Table 15

# 10.7. Reflow Cleaning Instructions

Without using *no-clean* solder we recommend cleaning the sensor surface after component assembly with nitrogen gas, distilled water or isopropanol to remove any flux residues. Do NOT use sodium hydroxide, other highly alkaline solutions or acetone as this would damage the anti-reflective coating on the glass surface. Ultrasonic chip cleaning is prohibited, as it can result in dust emission from cut surfaces.

#### MLX75027 VGA Time-of-Flight Sensor

PRELIMINARY DATASHEET



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